

ABSTRACT

ZHAO, WENXU. Headphone Driver Design with Inductive Coupled Interconnection. (Under the direction of Dr. Paul D. Franzon).

A fully inductive replacement for the standard TRS headphone jack was designed. The inductive headphone connector is composed of only two connections; a small inductor for data transmission surrounded by a larger inductor used to transfer power. The complete connector is approximately 4 mm by 6 mm on a 4 mil width and spacing two-layer PCB. The power channel couples a 200 MHz sine wave generated from the mobile device and is rectified in the receiver to a 1.2 V DC supply, which powers all the circuitry in the headphones. The power operating frequency and power transfer coils are co-optimized to give maximum power efficiency and limited crosstalk. The single data channel easily supports two serialized 16 bits 44.1 kHz audio channels at 1.41 Mbps with additional bandwidth for other channels as needed. Once the data is de-serialized into left and right audio, and is finally amplified by a Class-D power amplifier to drive the 32 Ω headphones. Simulations results of the complete transmitter, design in IBM's 0.13 μm 8RF process and consuming approximately 60 mW at peak, are presented along with a characterization of the channel.

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Headphone Driver Design with Inductive Coupled Interconnection

by
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DEDICATION

To my parents Chunming and Yuli

BIOGRAPHY

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LIST OF ABBREVIATIONS

TRS	tip, ring, sleeve
NRZ	non-return-to-zero
RZ	return-to-zero
TX	Transmitter
RX	Receiver
LCI	Inductive Coupled Interconnection
PCB	Printed Circuit Board
PA	Power Amplifier
PWM	Pulse-Width Modulation
PCE	Power Conversion Efficiency
PLL	Phase Locked Loop
VCO	Voltage Controlled Oscillator
PD	Phase Detector
LPF	Low Pass Filter

Chapter 1 Introduction

1.1 Motivation

The TRS connector (tip, ring, sleeve), first appeared in 1907[1], has been widely used for analog signal including audio [2]. A 3.5 mm TRS plug is shown in figure 1.1

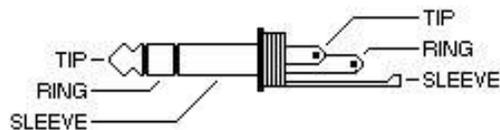


Figure 1.1 3.5 mm TRS plug

Though it has been used for more than 100 years, and nowadays it is being widely used on smart phones and portable audio equipments. There are several drawbacks with this type of audio connector: 1) relatively large area. Considering the rapid development of smart phone design and the growing battery area due to consistently growing requirement for more power, even the area of headphone plug is precious for designers, especially for the huge battery. 2) Not waterproof. 3) Limited breaking away possibilities. If the headphone plug is tugged, by someone tripping over the headphone wire, it will pull out the socket, probably damaging the connector or the socket. The Magsafe [3], which is a magnetically attached power connector introduced by Apple Inc, handle this situation very well.

A headphone driver with an inductive coupled interconnection is proposed in this work. This helps to overcome the above mentioned drawbacks. The entire design features a much smaller area, as well as a magnetically connection to prevent from breakaway.

1.2 Goal of this work

This work will demonstrate the use of non-contact inductive coupled interconnection as the transmission channel for both data and power for audio. A stereo headphone driver are designed, and will be fabricated and tested, with IBM 8RF 0.13 um technology, to run the standard 44.1 kHz sampling rate, 16 bits audio signal, providing 12 mW for each 32 Ω resistive load.

1.3 Thesis Overview

The remainder of this thesis is organized as follows. In chapter 2 background information is presented for the inductive coupled interconnection models used in this design. Chapter 3 discusses system level design considerations and design iterations. In Chapter 4 design details will be presented for each of the blocks, simulation results are shown, along with the layout view. Chapter 5 wraps up the work presented in this thesis and future work is proposed.

Chapter 2 Inductive Coupled Interconnect

Mick et al.(2002) presented the concept of Inductive coupled Interconnect [4], which enables multi-gigabit-per-second communication with high pin counts and low power consumption. Figure 2.1 shows an inductive coupled interconnection transceiver system.

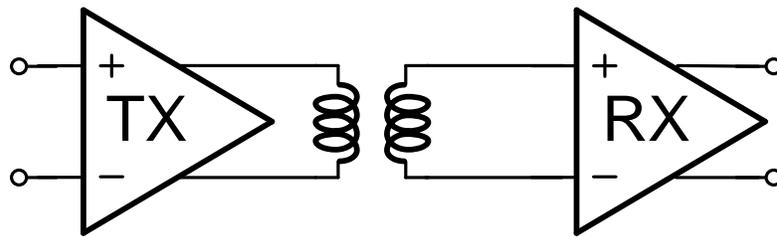


Figure 2.1 Inductive Coupled Interconnect Transceiver

A current mode transmitter circuit converts non-return-to-zero (NRZ) voltage signals into bipolar current swings. The current swings excite primary inductor and induce current pulses at the secondary inductor. A current mode receiver senses the current pulses, and regenerates NRZ voltage signals. Physical layout of the inductive coupled channel used in this design is shown in figure 2.2 (Contributed by Peter Gadfort and Evan Erickson)

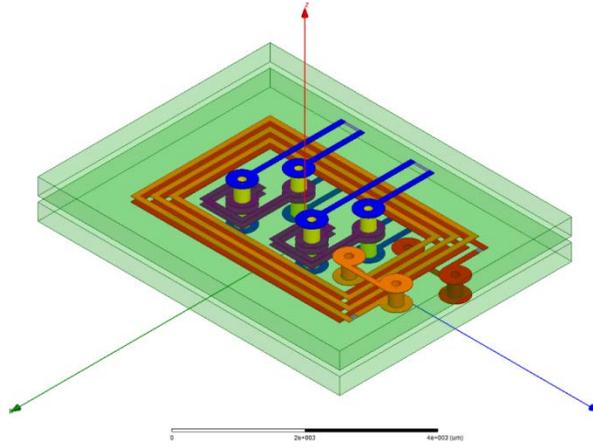


Figure 2.2 Physical Layout of Inductive Coupled Channel

The channels are mounted on two PCBs, separated by 25.4 μm . It consists of an outer larger channel with two inner smaller channels. Basic parameters for the three channels are shown

Table 2.1 Physical Dimension of Inductive Coupled Channels

	turns	shape	Width (μm)	Spacing (μm)	Height (μm)	Diameter (μm)
Outer	2	Rectangle	8	4	9	8281×4979
Inner	2	Rectangle	5	4	9	1981×1981

The channel is modeled in HFSS, corresponding S-parameter is extracted and simulated. Its frequency response from 1 kHz to 4 GHz is shown in figure 2.3

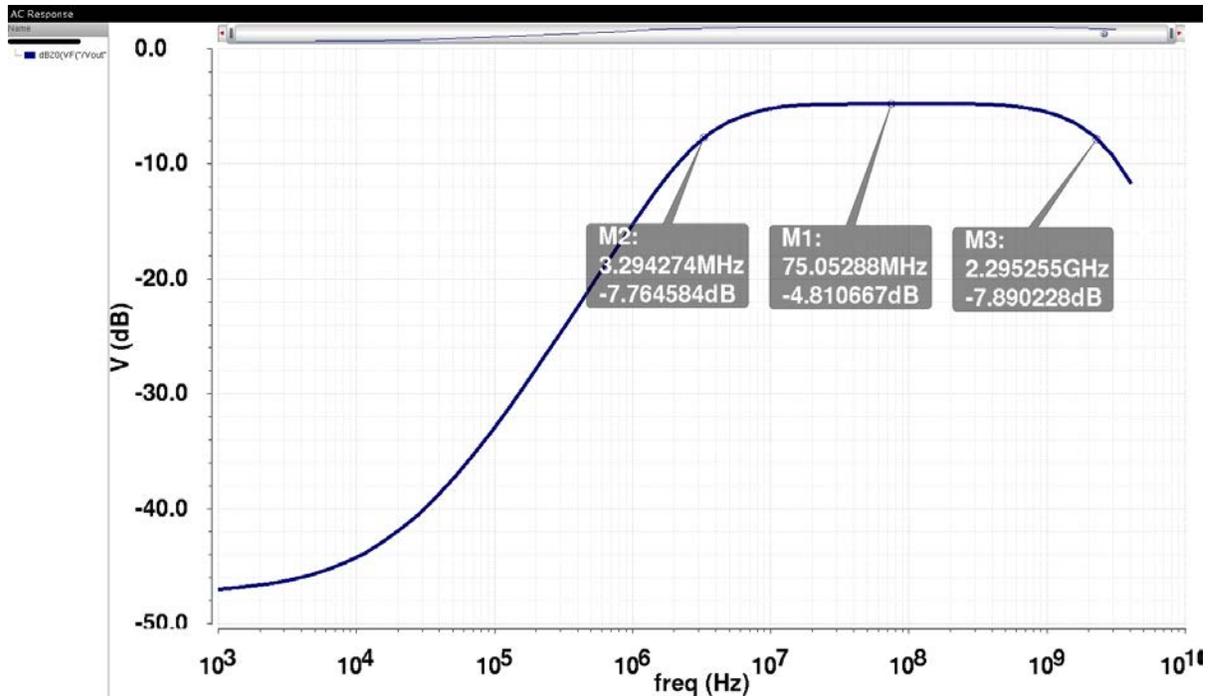


Figure 2.3 Frequency response of Inductive Coupled Channel

It is clear that the inductive coupled channel performs as a band pass filter, the 3 dB pass band ranges from 4 MHz to 2 GHz.

With a 200 MHz input sine wave, figure 2.4 and 2.5 show the input power, output power and power transfer efficiency as functions of load impedance. Note that peak efficiency is achieved with load impedance around 5 Ω .

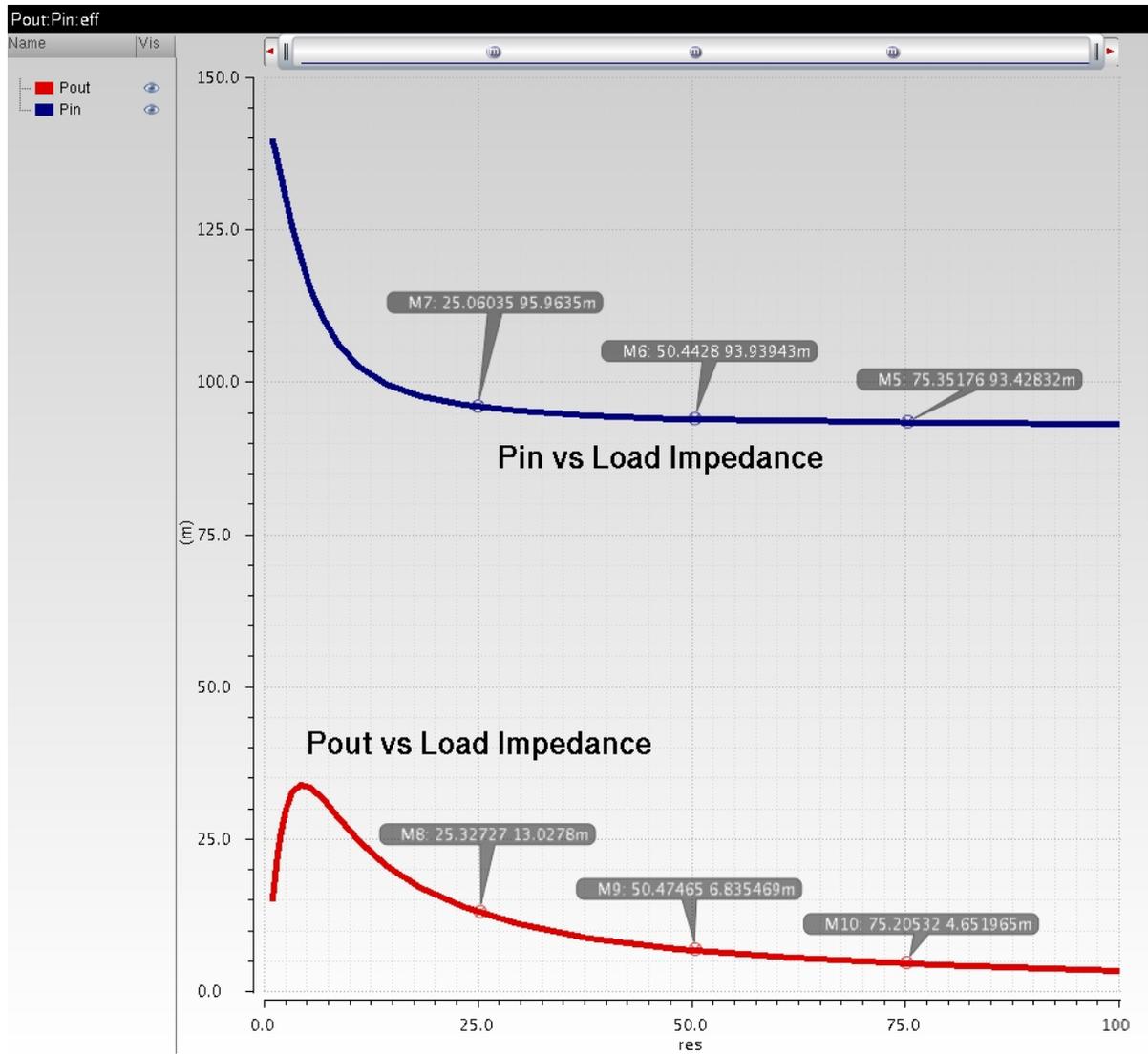


Figure 2.4 Input and Output power as functions of load impedance

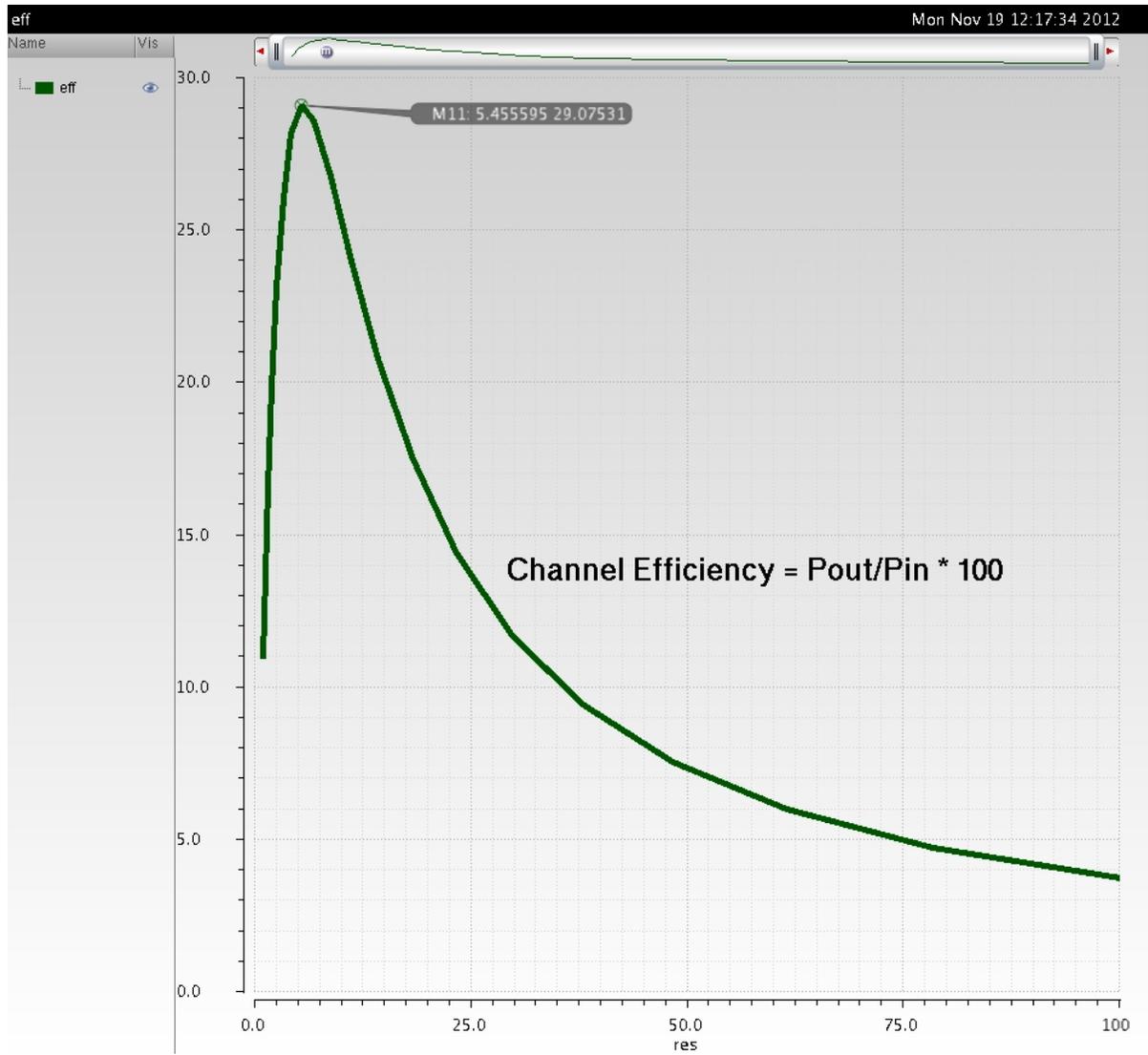


Figure 2.5 Power Transfer Efficiency as a function of load impedance

Figure 2.6 and 2.7 show input power, output power and power transfer efficiency's dependence on input amplitude. When input amplitude increases, the input and output power both increase, while the power transfer efficiency keeps constant.

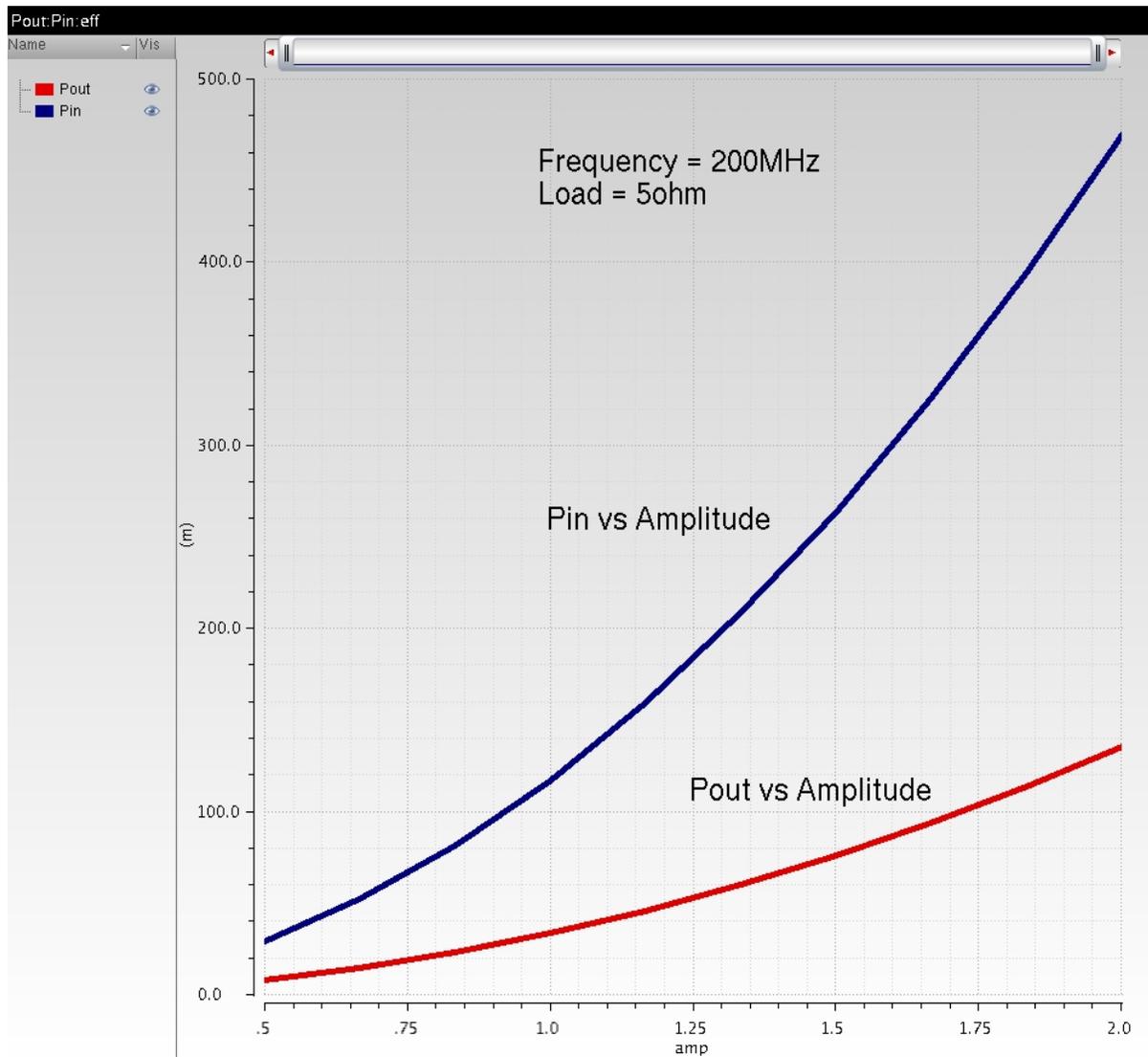


Figure 2.6 Input and Output Power as functions of input Amplitude

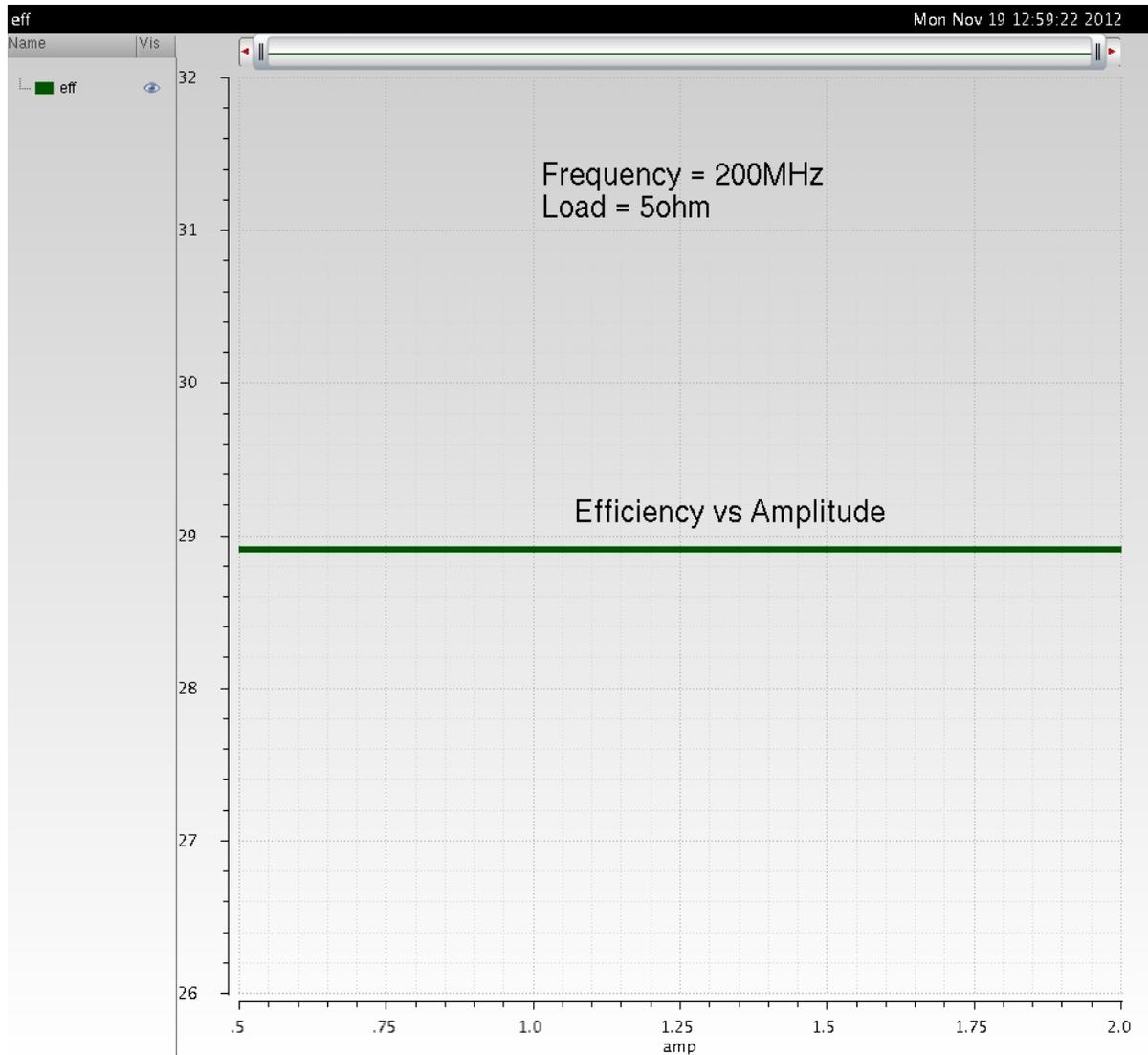


Figure 2.7 Power Transfer Efficiency as a function of input Amplitude

Figure 2.8 and 2.9 show input power, output power and power transfer efficiency's dependence on operation frequency. When input amplitude increases, the input and output power both decrease, while the power transfer efficiency peaks at around 190 MHz.

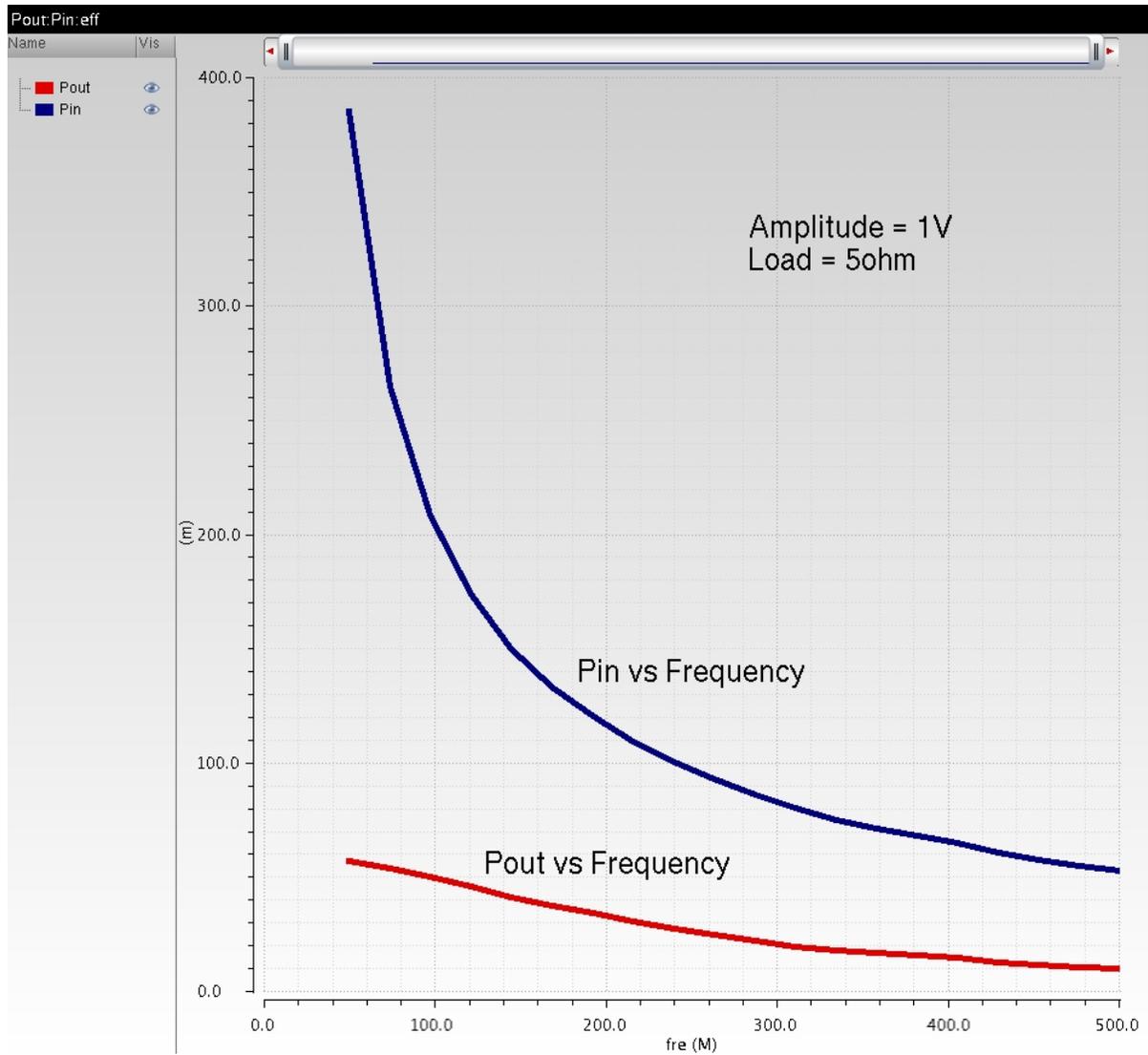


Figure 2.8 Input and Output power as functions of operation frequency

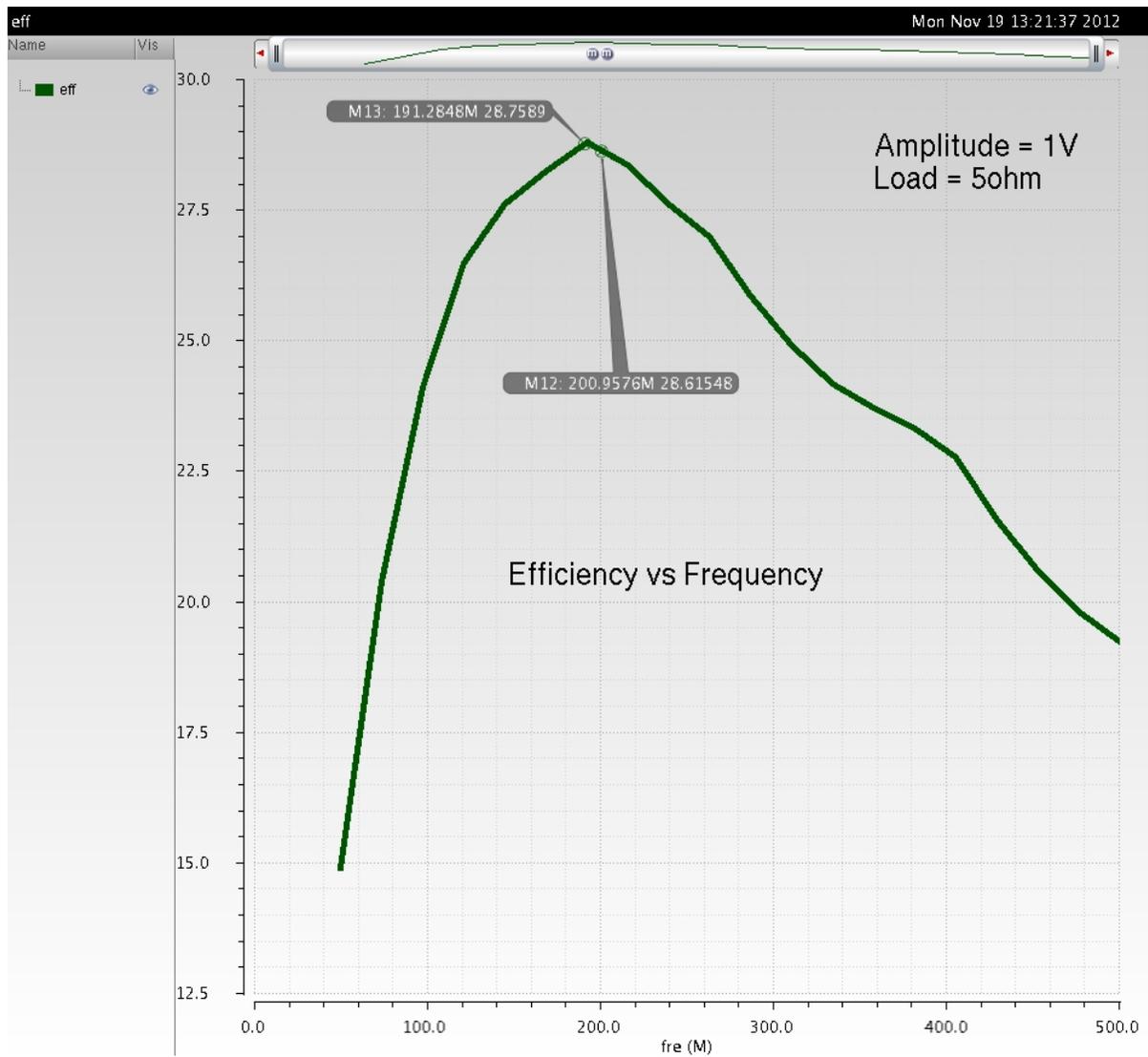


Figure 2.9 Power Transfer Efficiency as a function of Operation Frequency

Chapter 3 System Design

3.1 System Overview

When considering inductive coupled interconnect (LCI) to transmit audio signal; the first intuition is to send the amplified analog audio signal directly across it. In this case, the transmitter side of headphone does not need any changes from the current TRS design. However, this idea was abandoned due to the frequency character of the inductive coupled channel. As shown in chapter 2, the LCI we use operates as a band pass filter, whose pass band locates at MHz to GHz range. At frequency as low as audio, namely 20 Hz – 20 kHz, attenuation dominates. Instead, LCI is capable of transmitting digital data and they will be easily recovered at receiver side. As a result, the operations of analog to digital converting, power amplifying, which are usually handled at transmitter side in conventional TRS connector structures, have to be moved to the receiver side. Therefore, the processing of audio data through LCI ends up consisting of three main steps:

1. Sending sampled digital audio data across LCI
2. Data recovery
3. Converting the digital audio into analog audio signal, power amplifying it to drive the 32 Ω load

This is why two smaller channels are used: one for data and one for clock transfer.

Besides, power supply is also provided through LCI. Knowing that LCI blocks the DC

component of a digital signal, a near field power scheme is used here: the larger LCI channel transferring a high frequency sine wave, which will later be rectified into local DC voltage supply.

The first version of block diagram of system is shown in fig 3.1

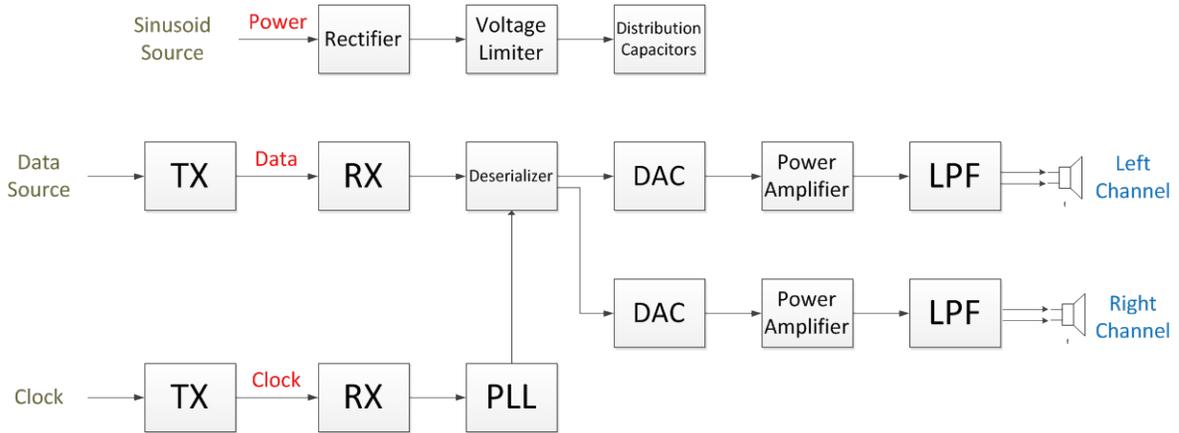


Figure 3.1 First version of system design (DAC and clock channel included)

A critical block in this proposed system is the power amplifier. Class D audio power amplifier (PA) is used here. Compared with linear audio PA classes such as Class A, B and AB, Class D PAs have higher power supply efficiency. In linear PAs, significant amounts of power are lost due to biasing elements and the linear operation of the output transistors [5]. Because the transistors of a Class D amplifier are simply used as switches to steer current through the load, minimal power is lost due to the output stage. The most basic topology utilizes Pulse-Width Modulation (PWM) with triangle wave oscillator. Figure 3.2 shows a simplified block diagram of Class D PA [6]

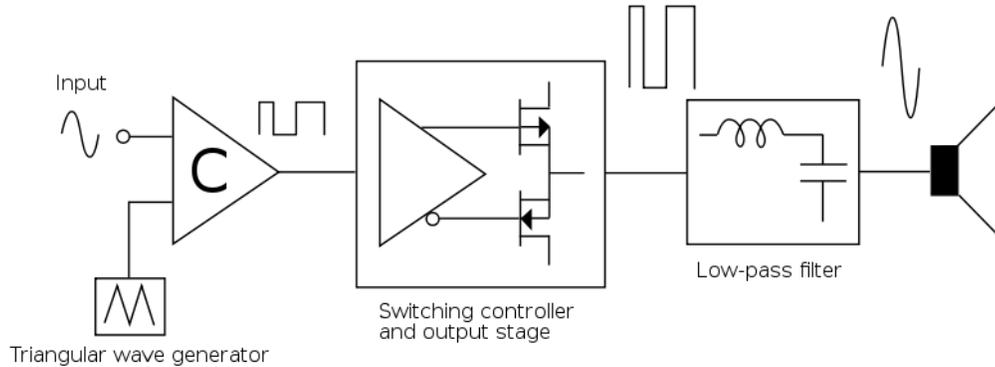


Figure 3.2 Block Diagram of Conventional Class D Power Amplifier

The input analog audio signal is pulse-width modulated by the triangular signal, generating a square wave, of which low-frequency portion of the spectrum is the wanted output signal. Then the binary wave-form is amplified by switching the power devices, which is a cascade of inverters whose final transistors have a large W/L ratio to obtain low output impedance. Before driving the load, a passive low pass filter removes the unwanted high-frequency components. The switching frequency is typically chosen to be ten or more times the highest frequency of interest in the input signal.

Note that in order to use this type of Class D PA, the input audio data has been converted several times between analog and digital forms, as shown in figure 3.3



Figure 3.3 Audio signal processing path

One possible way to reduce the system complexity is to implement fully digital processing of audio signal, eliminating the use of DAC. This indicates that generating PWM

signal directly from digital audio signal, which will also reduce the power budget and ease the design effort for power supply circuits. The detailed method of generating PWM signal from digital input will be discussed in chapter 4 circuit implementation. The second version of block diagram of system is shown in fig 3.4

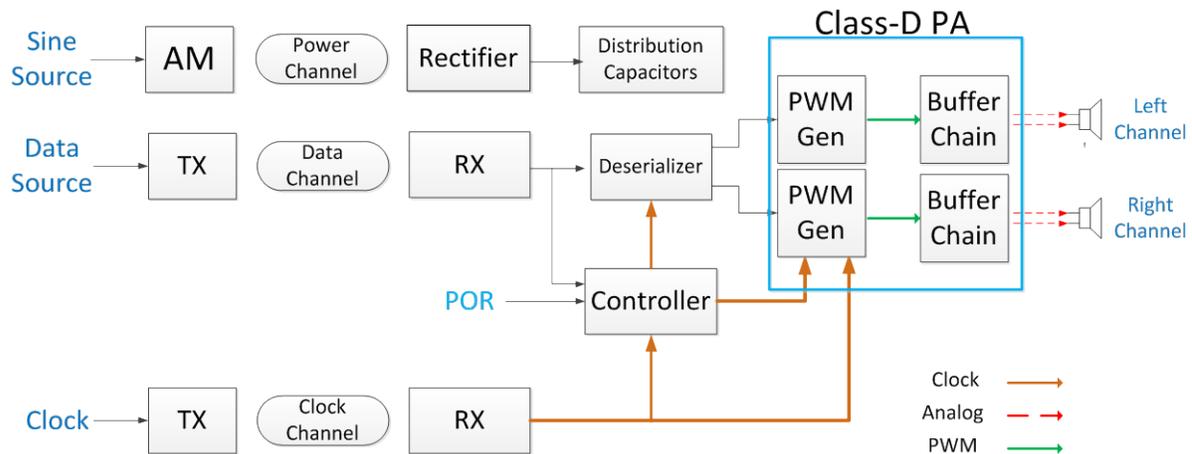


Figure 3.4 Second version of system design (clock channel included)

3.2 Synchronization and Alignment Scheme

Due to constrained number of pads on chip and the existing synchronization flaw with previous version of design, the clock is recovered from data instead of transferred through a separate channel. This brings up two important design considerations in systems with transceiver, we now require a synchronization scheme and alignment scheme.

There are three basic timing models used for communication [7] --- (1) system synchronous, (2) source synchronous and (3) self synchronous. Previous version of system is

source synchronous, which sends a copy of the clock along with the data. It introduces asynchronous issues when clock speed keeps increasing. The clock data recovery scheme, which falls into the self synchronous model, is more robust against source synchronous method. By adding the PLL-based clock recovery circuit, clock channel can be eliminated.

Alignment is another significant aspect in series link design. The deserializer at receiver side is clocked by such an alignment signal to accurately recognize data boundaries in the serial data stream. By adding an external reset signal and internal counter, and with the help of local generated clock, alignment can be easily handled.

The finalized system design is shown in figure 3.5

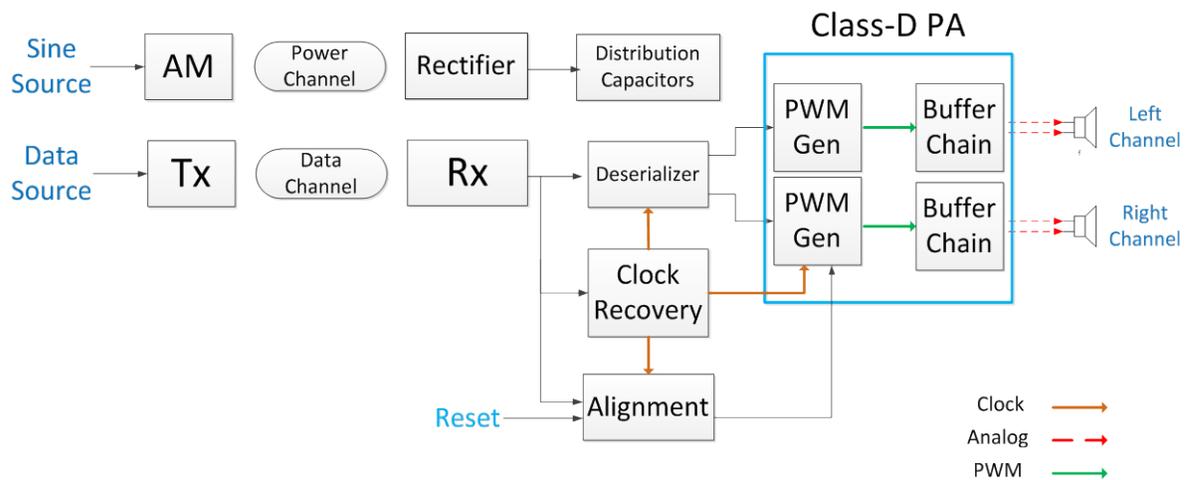


Figure 3.5 Final block diagram of system design

Chapter 4 Circuit design

4.1 Pulse signaling in LCI --- Transceiver Design

A LCI transceiver, shown in figure 2.1, utilizes current mode pulse signaling [8]. Upon the input NRZ data, a differential driver controls the directions of current swing in the primary inductor, and creates an alternating magnetic field that induces current pulses in the secondary inductor. A differential receiver senses the current pulses, converting them into voltage pulses, then amplifies and latches into original NRZ data.

4.1.1 Transmitter

A current mode Transmitter is shown in figure 4.1

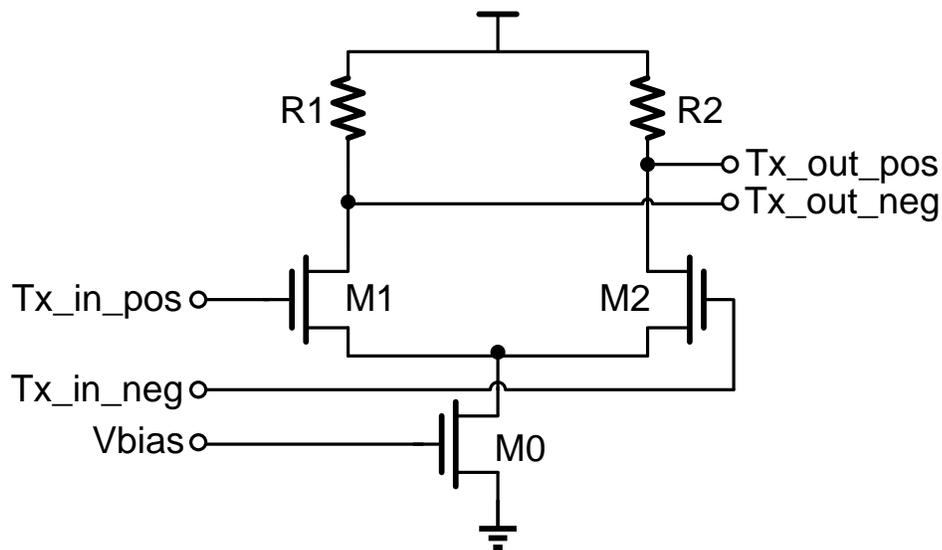


Figure 4.1 Differential Current Mode Transmitter

The transmitter should generate high edge rate to signal through the inductive coupled channel, as well as providing accurate impedance match. A differential current mode transmitter has the advantages of generating signal with true balanced rising/falling edges, easier to impedance match. The downsides of current-mode driver compare to voltage-mode, are less power efficient and slower slew rate.

The output impedance of this differential common source driver, R_{out} is

$$R_{out} = R_1 \parallel r_o$$

Where r_o represents output resistance of input NMOS and R_1 is termination resistance. By sizing M1, M2 and R_1 accordingly, the output impedance is around 50Ω which matches the characteristic impedance of the primary side coil. In actual implementation, multiple digitally controlled current sources are added, which provides the ability to discretely control the driving force accordingly.

Implementing in $0.13\mu\text{m}$ CMOS technology with a 1.2 V power supply, the power consumption of the differential current-mode driver is around 3 mW .

4.1.2 Receiver

The low swing complementary pulse receiver [8] includes three stages shown in figure 4.2: sensing, amplifying and converting. It senses current pulses on secondary coil, converting them to voltage pulses, amplifying to rail-to-rail RZ signal, and converts back to digital NRZ signal.

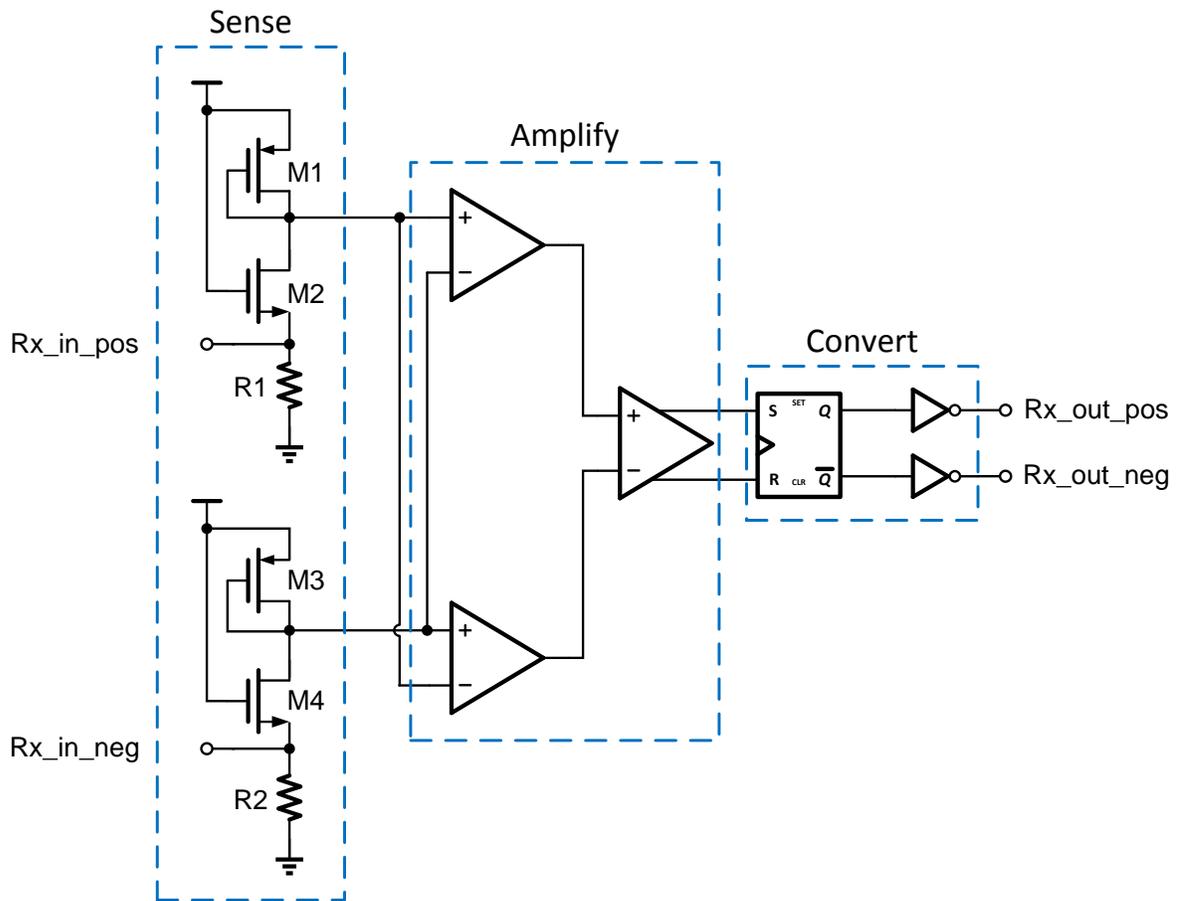


Figure 4.2 Pulse Receiver

The input termination resistor matches the characteristic impedance of secondary coil and converts the input current pulses into voltage pulses. A common gate single stage amplifier is used in the sensing stage, due to its relatively low input impedance. Since the input DC point at secondary coil is almost at ground, the common gate not only amplifies the voltage pulses, but also leverages DC point onto a reasonable value for the next stage amplifier to work. There are several trade-offs here for the sensing stage design. Regardless of impedance matching, the smaller the termination resistor, the larger the converted voltage

pulse will be while lowering DC operating point at its output and more power consumption. For the final implementation, a matched termination resistor is chosen. Another trade-off lies between the DC operating point of output node and gain of first stage. By increasing the size of diode connected PMOS load M1, a higher DC operating can be achieved while lowering the small signal gain. In actual design, the sensing stage and amplify stage are co designed to achieve a high gain with relatively wide bandwidth.

The Rx amplifying stage includes a pair of self-biasing, source coupled differential amplifier [9] and a symmetric Chappell amplifier [10]. The tradeoff is between bandwidth and gain. To amplify voltage pulses, a width bandwidth lower gain amplifier is preferred, to minimize amplifier introduced distortion.

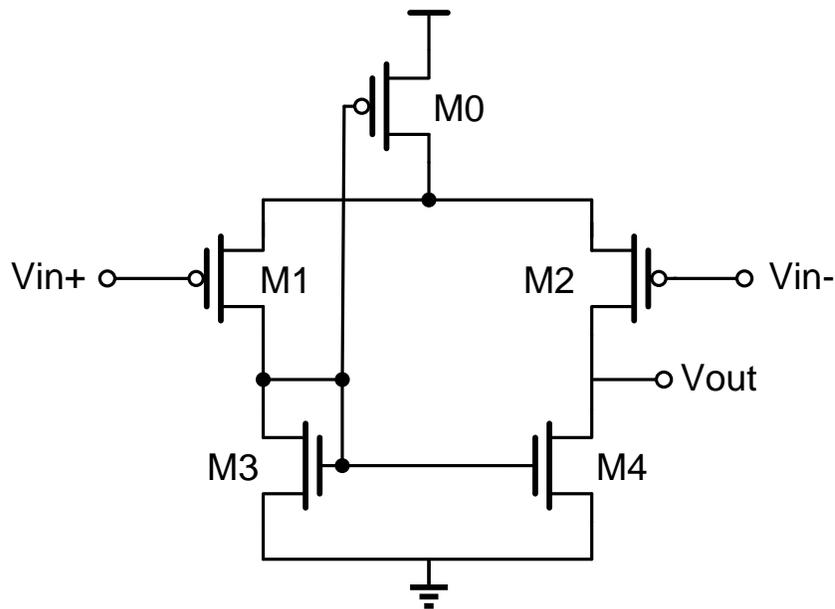


Figure 4.3 Source Coupled Differential Amplifier

The source coupled differential amplifier is shown in figure 4.3. Note that the common mode input voltage is quite low due to previous stage, the type of PMOS as input

devices is chosen instead of NMOS. N-type current mirror is loaded to provide single-ended output. The PFET current source is biased by the gate signal from the NMOS load. This results in negative feedback that drives the bias voltage to the proper operating point [9]. If the bias current is too low (high), the drain voltage rise (fall), increasing (decreasing) the bias voltage. The quiescent power dissipation is around 240 uW.

The gain bandwidth plot is shown in figure 4.4

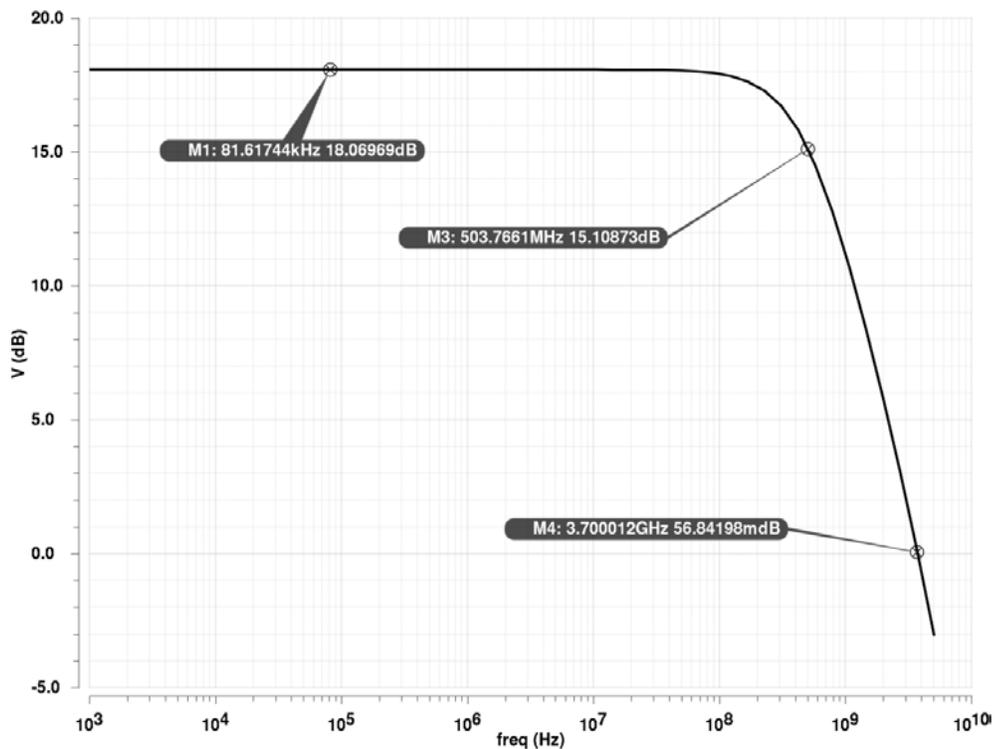


Figure 4.4 Frequency response of source coupled differential amplifier

Schematic of A symmetric Chappell amplifier [10] is shown in figure 4.5,

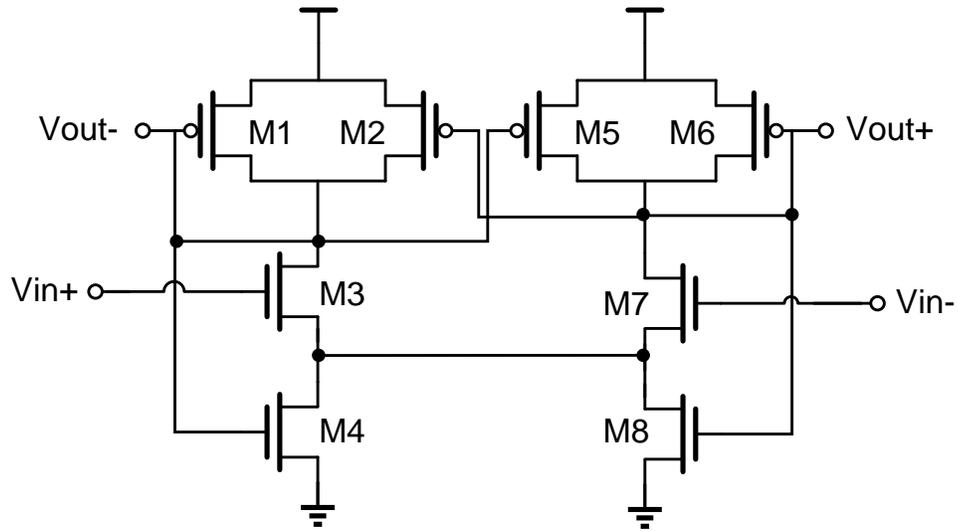


Figure 4.5 Schematic of Chappell Amplifier

This circuit uses two current mirrors for the load, with each mirror driving one of two current source devices. The negative feedback control of the bias current is the same as for the single-ended Chappell amplifier. The signal at the differential output should be rail-to-rail pulses to drive next sampling stage. The quiescent power dissipation is around 400 μ W.

The gain bandwidth plot is shown in Fig 4.6

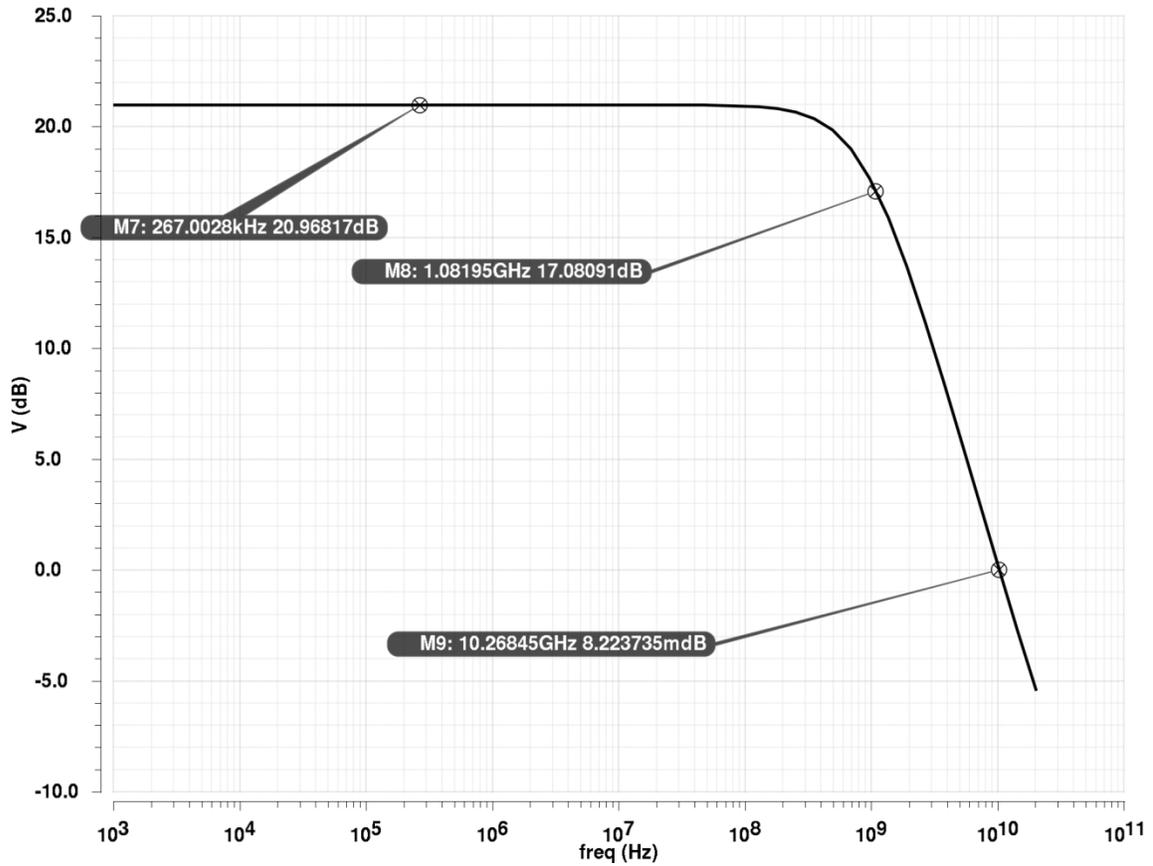
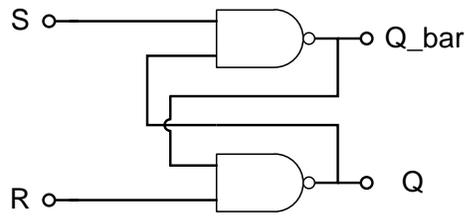


Figure 4.6 Frequency response of Chappell Amplifier

A RS latch is used to converting the RZ voltage pulses into NRZ digital signal, shown in figure 4.7. Figure 4.8 shows the waveforms in each stage of transceiver when a 100 MHz clock signal is transferred.



RS Latch

Figure 4.7 Schematic of RS Latch

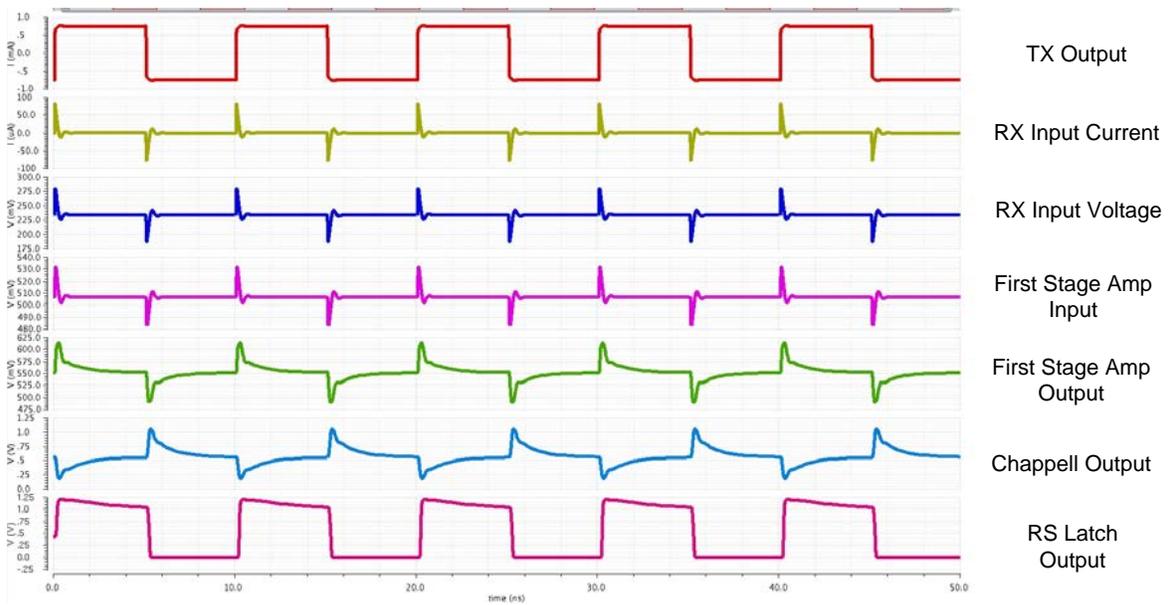


Figure 4.8 Signaling of Pulse Receiver

4.2 Deserializer and Alignment

The stereo audio signal, which includes two serialized 16 bit 44.1 kHz channels, is received and recovered by the differential pulse receiver. Then the signal is sampled by the

recovered clock at the speed of 1.41 MHz ($44.1 \text{ kHz} \times 32$), and de-serialized by a Serial-In Parallel-Out block shown in figure 4.9

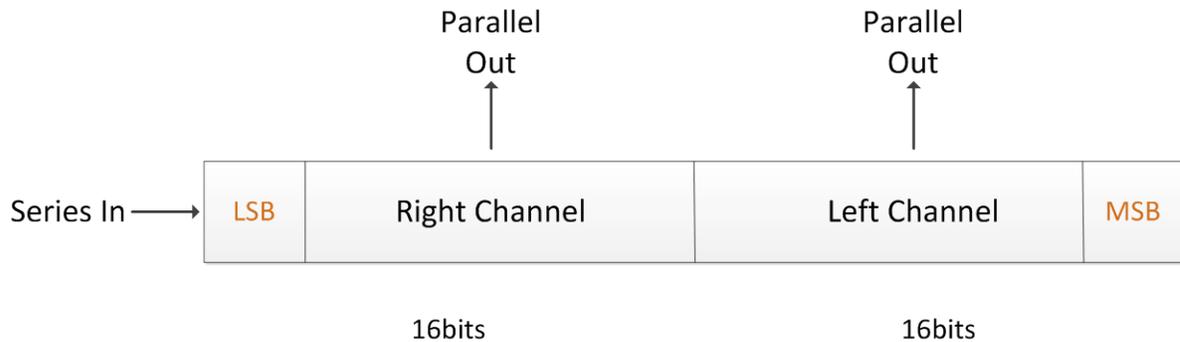


Figure 4.9 Serial-In Parallel-Out

A 32 bits shift register performs the function of SIPO. Conventional low speed master-slave flip-flops are used in it. The series in clock is generated by clock data recovery at 1.41MHz. And the parallel out clock is provided by the Alignment block.

As mentioned before, the alignment of SIPO is done at every time the system restarts. By adding all 00...01 before real audio data and resetting the flag value, the flag will set to high and keeps high whenever the first 1 comes. Flag is used as the reset signal of the following divide-by-32 clock divider. As long as flag goes to high, clock divider will generate the reload signal, which is a 44.1 kHz clock, used for SIPO output latching. The schematic and timing diagram of this alignment scheme is shown in figure 4.10

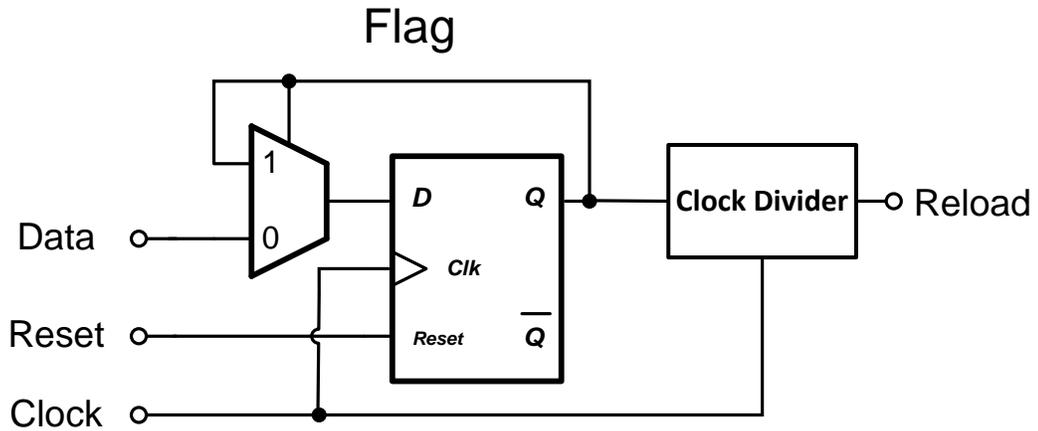


Figure 4.10 (a) Schematic of Alignment

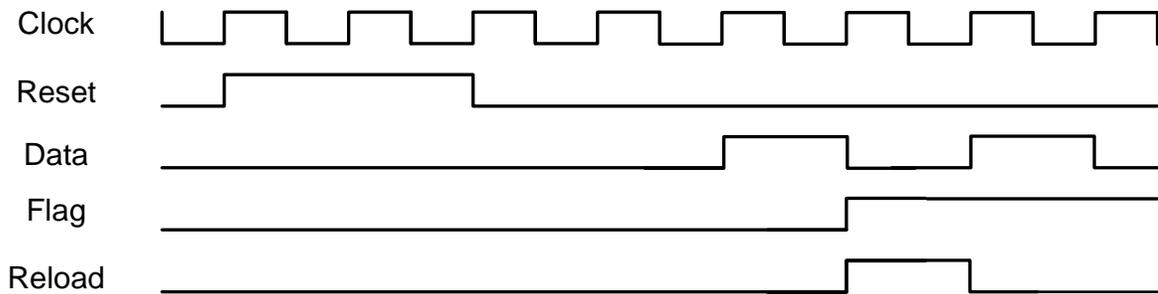


Figure 4.10 (b) Timing Diagram of Alignment

4.3 Class D Power Amplifier

4.3.1 Introduction

Upon the two channel 16 bits audio signal received and de-serialized, they are power amplified by two Class D PAs to drive the 32 Ω load.

Class D power amplifier is used here instead of linear audio power amplifier such as A, B, and AB. In linear amplifiers, significant amounts of power are lost due to biasing elements and the linear operation of the output transistors. Because the transistors of a Class D amplifier are simply used as switches to steer current through the load, minimal power is lost due to the output stage. The Class D PA can also be advantageous due to its ability to directly interface to digital input signal, thereby eliminating the need for a digital-to-analog converter. Class D amplifier work by generating a square wave of which the low-frequency portion of the spectrum is essentially the wanted output signal, and of which the high frequency portion serves no purpose other than make the wave-form binary so it can be amplified by switching the power devices.

All Class D PA encode information about the audio signal into a stream of pulses. Generally, the pulse widths are linked to the amplitude of the audio signal. The most common Class D power amplifier comprises of Pulse-Width Modulation (PWM) process and an output stage. Conceptually, PWM compares the input audio signal to a ramping waveform that runs at a fixed carrier frequency, as shown in figure 4.11.

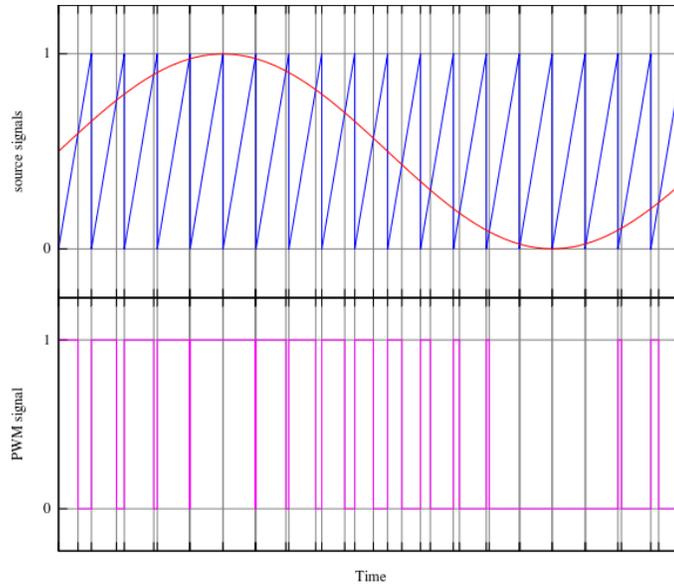


Figure 4.11 Pulse Width Modulation [11]

There are basically two types of Class D PA corresponding to the form of input audio signal. Analog Class D PA generates ramping signal with an oscillator and samples the analog input audio signal by comparing it with the carrier, using a high resolution comparator. This kind of implementation requires digital to analog converter if inputting digital audio signal.

Digital Class D PA samples input audio data, and generates PWM signal by algorithmic-based processes. The reported methodologies to generate the PWM pulse signals in a digital PWM include uniform process [12], linear interpolation (LI) [12], pseudo-natural PWM [13], static-filter PWM [14], weighted PWM and its variants [15], derivative PWM [16], parabolic correction PWM [17], prediction correction PWM [18]. The hardware requirement of these algorithm-based processes is relatively complex, and the power dissipation is prohibitive for this power hungry design, so does the DAC design in analog

Class D PA. The uniform process [12], which is used in this design, despite its high total harmonic distortion (THD), offers a simpler design and less power consumption for this demonstrative type of work. The triangular carrier in uniform sampling can be regarded as an up/down digital counter, as shown in figure 4.12

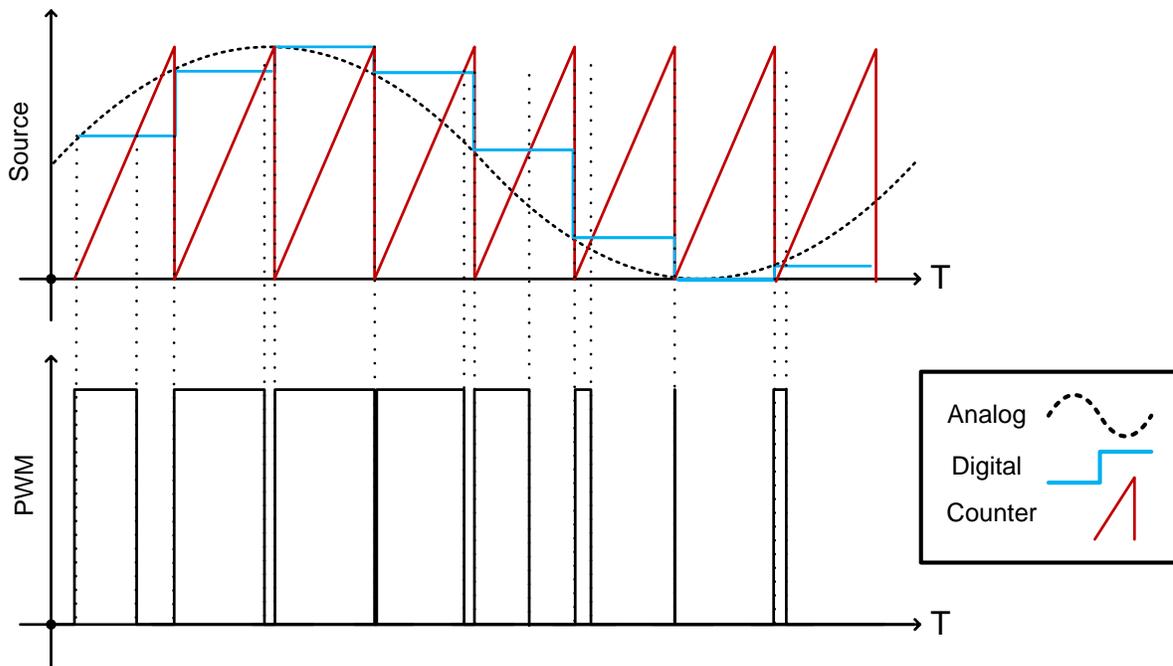


Figure 4.12 Single-sided trailing edge uniform sampling

Similar to conventional Class AB amplifiers, Class D PA can be categorized into two topologies, half-bridge and full-bridge configurations [20], as shown in figure 4. 13. Full-bridge provides better performance, 1) the bridge topology can cancel the even order of harmonic distortion components and DC offsets, 2) it allows the use of ternary modulation [19], which results in a higher power efficiency and eliminating the need of LPF.

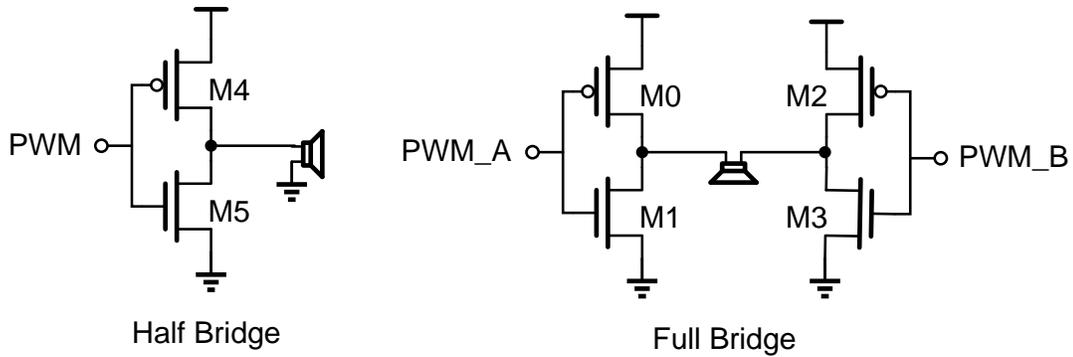


Figure 4.13 Half Bridge and Full Bridge configurations of output stage in Class D Power Amplifier

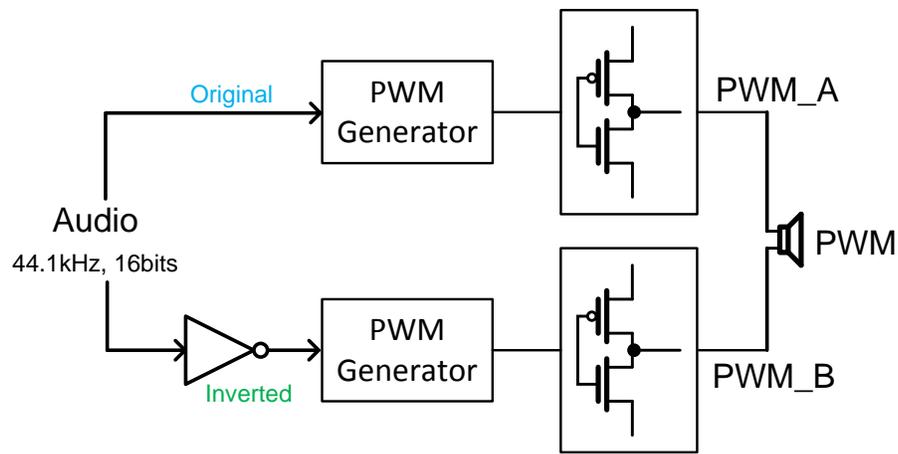


Figure 4.14 Block diagram of Ternary modulation

In ternary modulation, as shown in figure 4.14 and figure 4.15, original digital audio signal and its complementary value are fed into two PWM generators, generating two binary signals that, when subtracted, generated the three level value. In ternary modulation, there are only current pulses flow through the load, while in conventional binary PWM, there is always DC current flows through the load. This is essentially increasing the power efficiency of Class-D PA.

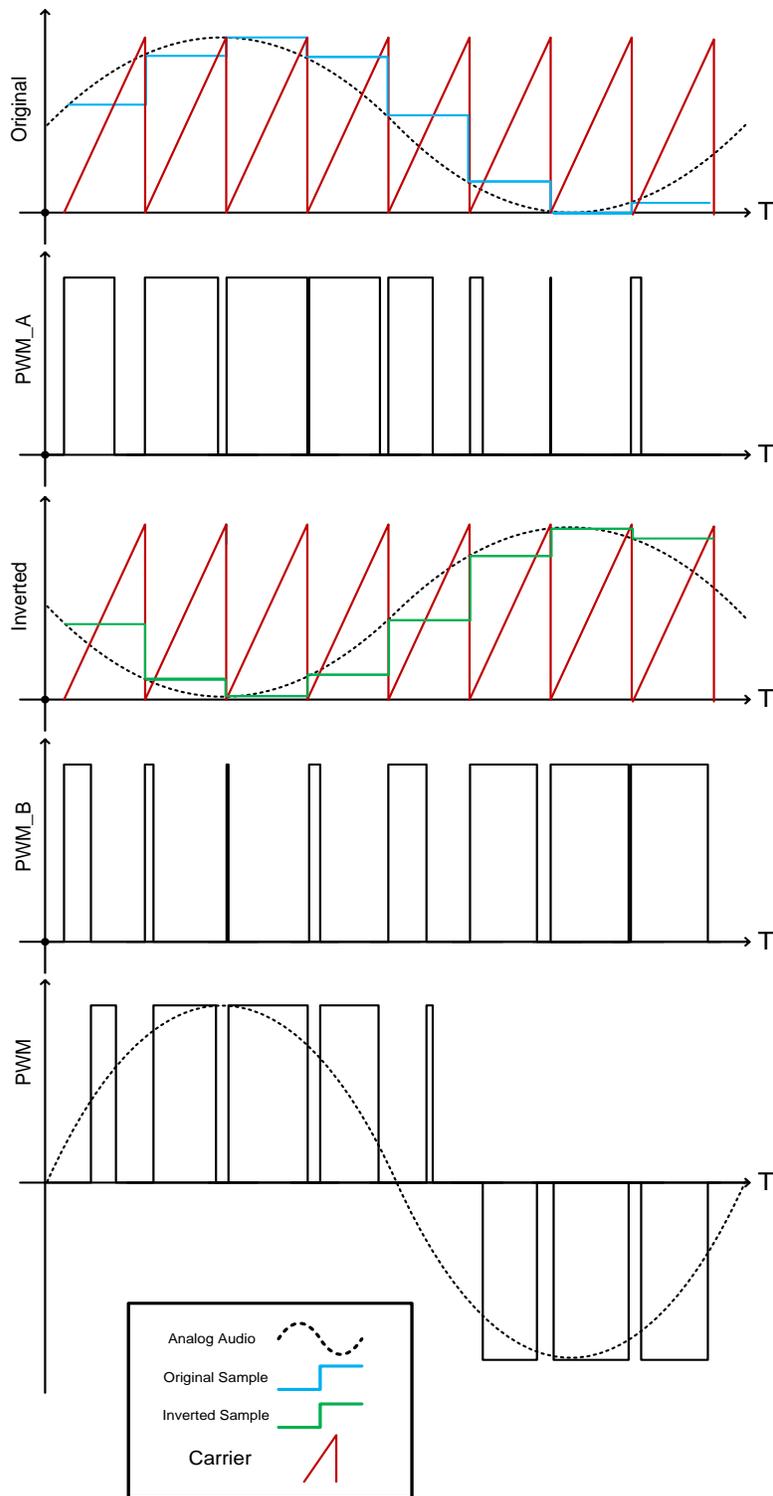


Figure 4.15 Waveforms in Ternary Modulation

4.3.2 Block Implementation of PWM

A hybrid PWM pulse generator [22] is implemented here, shown in figure 4.16. It comprises faster clock method and tapped-delay-line method. In digital system, PWM signals are typically created by using a faster clock method, and the counter clock frequency is chosen to be 2^N times the sampling frequency, where N is the number of bits of input data. In this design, if implementing faster clock method, the counter clock speed = $44.1 \text{ kHz} \times 2^{16} = 2.89 \text{ GHz}$. It results in a tougher PLL design and more power consumption, which is not acceptable in this design. One way to significantly reduce clock speed is to use a tapped delay line [21]. The essential components of a tapped delay line PWM circuit are the delay line and a multiplexer shown in figure 4.16. An M bits tapped delay line can reduce the clock speed by $1/2^M$. In this design, hybrid of counter clock method and tapped delay line method are implemented. The 16 bits audio data is partitioned into 13 bits most significant portion (MSP) and a 3 bits least significant portion (LSP), and they are the inputs to a down counter and a tapped delay line. Thus, the counter clock speed reduced to $44.1 \text{ kHz} \times 2^{13} = 361 \text{ MHz}$.

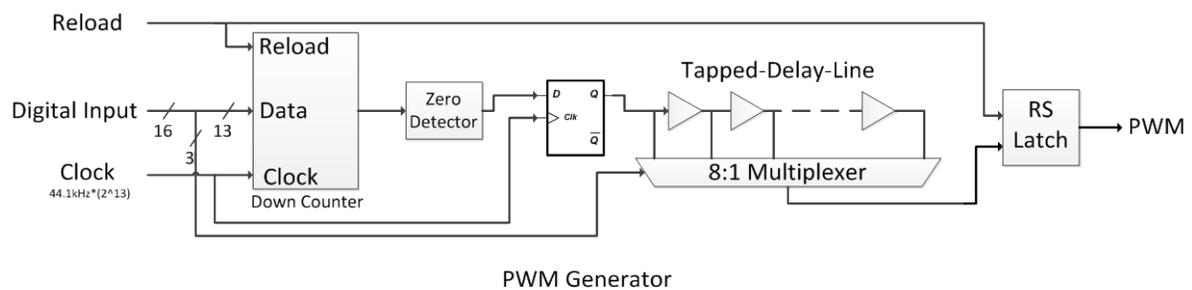


Figure 4.16 Hybrid PWM Generator

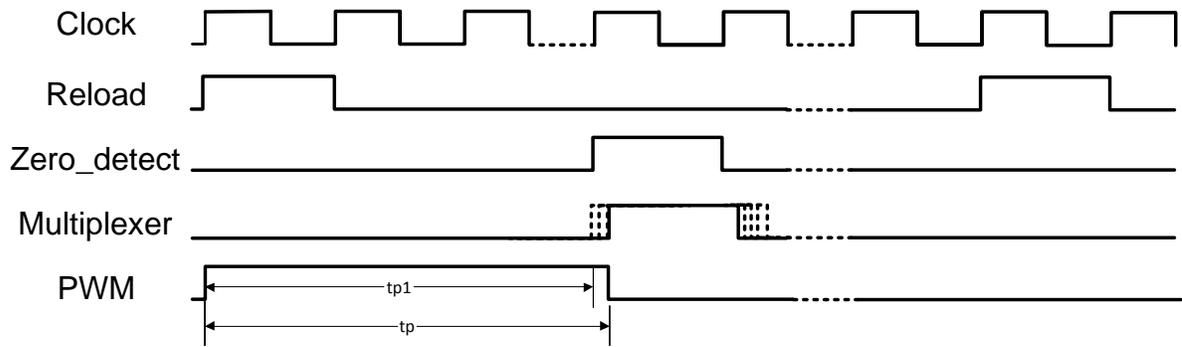


Figure 4.17 Timing diagram of hybrid PWM generator

The timing diagram in figure 4.17 shows how it works. The reload clock and counting clock are set at 44.1 kHz and 361 MHz, respectively. The PWM signal set to high on the rising edge of Reload, when new 16 bits of input value are loaded in. then the down counter will commence counting down the 13 bits MSP to zero. When the counter reaches zero, the 3 bits tapped delay line is initiated. The 3 bits tapped delay line is divided into eight equal clock periods and selected by an 8 to 1 multiplexer whose output depends on the value of LSP. The overall PWM pulse width is equivalent to the 16 bits digital value.

The total delay of the tapped delay line is adjusted so that the total delay is equal to the counter clock period. By sizing the CMOS inverters appropriately, the propagation delay can be adjusted. The ideal propagation delay of each stage should be $T = 1/2.89 \text{ GHz} = 346 \text{ ps}$.

4.4 Clock Recovery

4.4.1 Introduction

Due to constrained number of pads in this design, clock signals used in transmitter side have to be recovered from data and generated using PLL. There are two clocks needed, the 1.4112 MHz ($44.1 \text{ kHz} \times 2^5$) sample clock f_s for deserializer and 361 MHz ($44.1 \text{ kHz} \times 2^{13}$) counter clock f_c for PWM generator.

The sample clock can be recovered from the audio data while the sample clock will be generated with an integer-N frequency synthesizer, which $N = 2^8$. Combining these two structures together, a clock recovery circuit with an N divider is able to recover the sample clock and generate the counter clock as well, as shown in figure 4.18

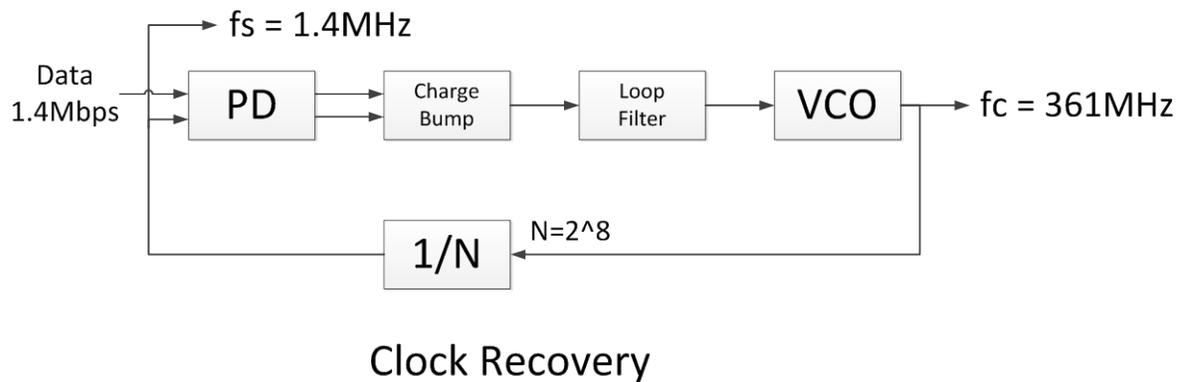


Figure 4.18 Block diagram of clock recovery

The proposed PLL based clock recovery circuit consists of a phase detector, a charge pump, a loop filter, a VCO, and a divider. In the locked condition [23], the phase detector produces an output whose dc value is related to phase difference between recovered clock

and input data. The charge pump converts voltage into current, allowing the loop filter suppresses high –frequency components in the PD output, generating a DC value to control the VCO frequency. The VCO oscillates at a frequency, which divided by N, equal to the input data speed and with a same phase difference as previous cycle.

4.4.2 Phase Detector

A conventional phase detector used in PLL is a circuit whose average output is linearly proportional to the phase difference. However, in clock data recovery scenario, the spectrum of random data exhibits a null at the bit rate [24], and the phase detector used for periodic signals may completely fail if they sense random data. Thus the PD for random data must provide two essential functions: 1) data transition detection and 2) phase difference detection.

A phase detector can be classified as linear or binary type according to the clock extraction method. The linear PD detects both the magnitude and the polarity of the phase error whereas the binary PD detects the polarity only. Both of them produce a zero output for non-transitions. Compared to binary PDs, linear PDs result in less charge pump activity, smaller ripple on the oscillator control line, and hence lower jitter [25]. On the other hand, the linear phase detector suffers from bandwidth limitation, which limits its usage in high speed CDRs.

The binary PD generates up/down signals corresponding to the phase error between the internal clock and input data. This type of PD is represented by the Alexander (Bang-bang) type of PD, shown in figure 4.19 (inside red rectangle). In the multi-Gbps regime, the

advantages of binary PDs (simplicity and accuracy) overcome the drawbacks of nonlinearity and self-generated jitter.

In this design, Alexander PD is used and modified into a linearized version, shown in Fig. The Alexander PD operates as follows: for any data transition, if the current sample value agrees with previous falling edge sample is early, if the current sample value agrees with next falling edge sample is late. The detailed timing diagrams for both late and early cases are shown in figure 4.20.

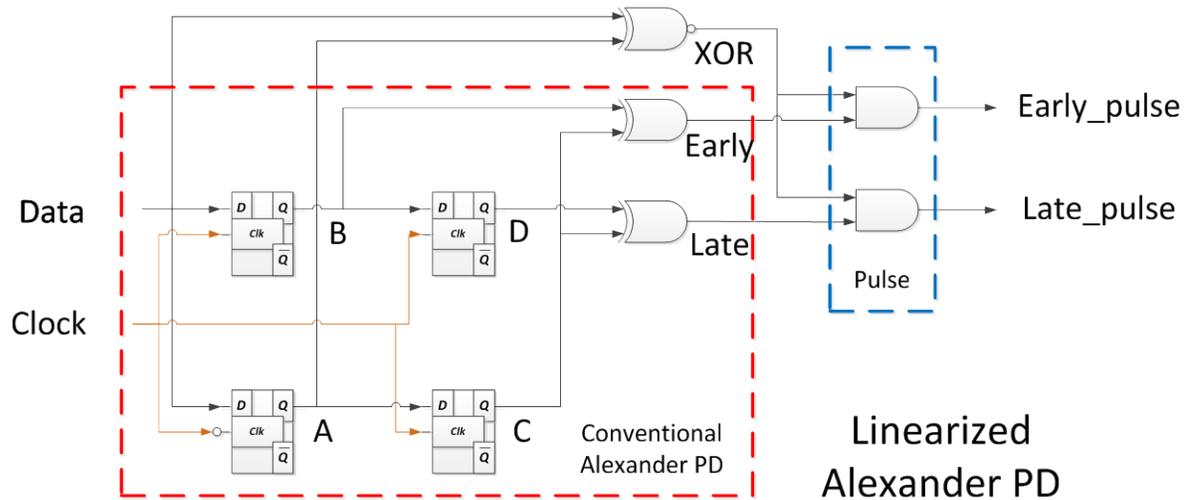
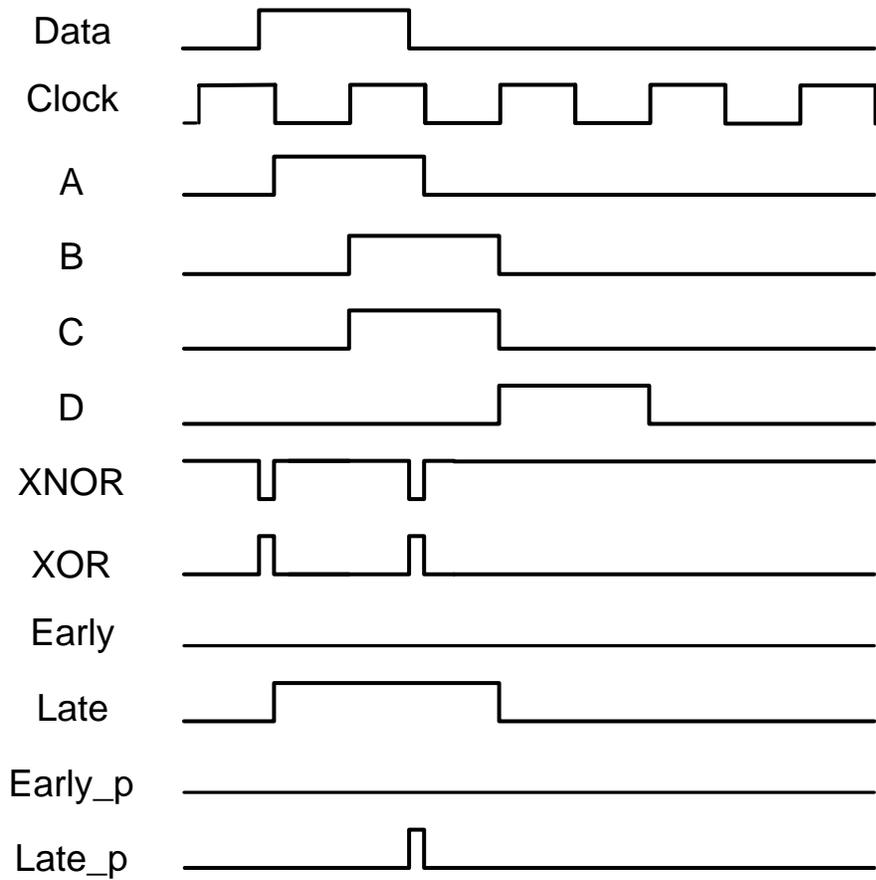


Figure 4.19 Linearized Alexander Phase Detector



Late Case

Figure 4.20 (a) Timing diagram of sampling after mid point

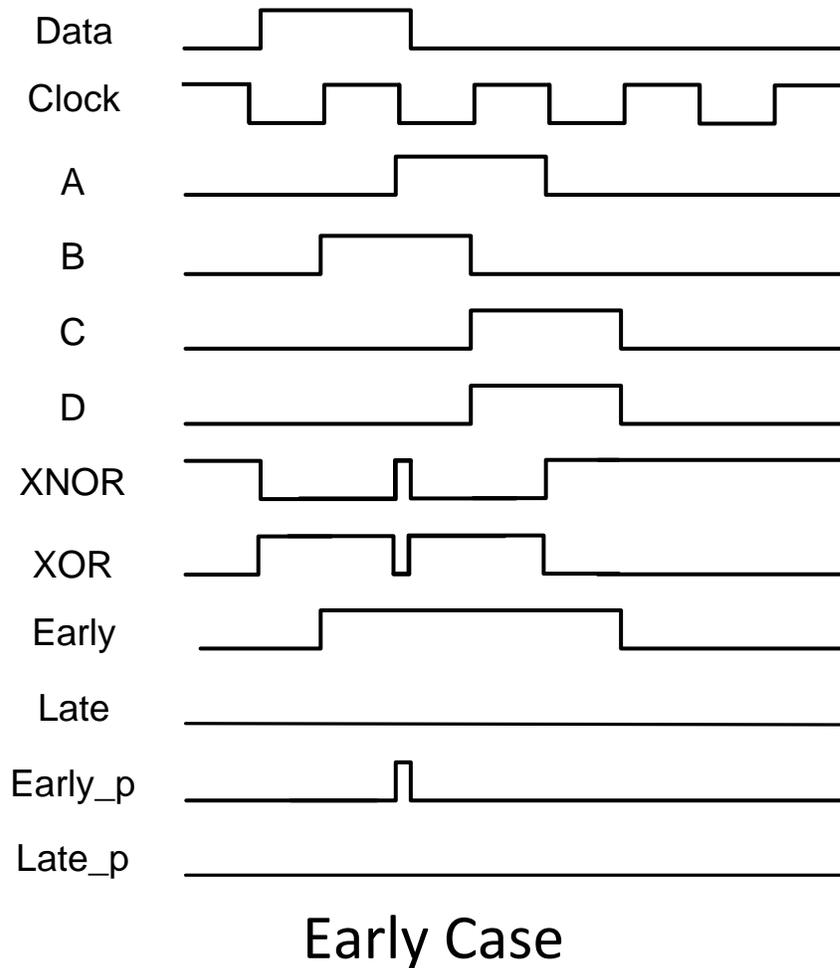


Figure 4.20 (b) Timing diagram of sampling before mid point

The binary characteristic of Alexander PD also affects the steady-state behavior of Clock Recovery Circuit [26]. The digitally feedback feature is not able to converge to a single state due to the discontinuity of quantization process even if the difference of input and output is close to zero. In steady-state, the system exhibits bounded periodic oscillations at the output in manner of dithering the quantized output to be close to desired finite value. In this design, in order to reduce the impact of this limit cycle, the two outputs of conventional

Bang-bang PD, are AND with a linear term --- the mismatch between data and clock (named XOR figures and timing diagram), to linearize the outputs.

4.4.3 Charge Pump & Loop Filter

The charge pump circuit comprises of two transconductance devices that are driven with Early and Late outputs of phase detector, converting the digital phase error voltage into charging or discharging current shown in figure 4.21 [27]. The choice of G_m is more related to the stability of the close loop. Note that charge-pump current (or G_m) provides gain for the close loop, it should be set relatively small to meet the stability requirement.

The combination of charge pump and C1 is an integrator that generates the average of Early or Late pulses, which adjusts the oscillating frequency of VCO. Since there is another integrator in VCO, the loop gain of this Type-II PLL has two poles at origin, thus, the closed loop system is unstable. In order to stabilize the system, a zero is introduced in the loop gain by adding a resistor R in serial with that capacitor.

To increase the out-of-band attenuation, an additional pole is created by adding a secondary capacitor in parallel with the RC [28]. The pole, with a time constant of RC2, filters high frequency ripples. The value of secondary capacitor is limited by stability and filtering requirements.

In S domain,

$$F_{LF}(s) = \frac{1}{s} \frac{(s + \frac{1}{C_1 R})}{(s + \frac{1}{(C_1 || C_2) R})}$$

As shown in above expression, C_1R defines the added zero and C_2R defines the added second pole. The value of C_2 should be set relatively small to minimize its effect on the close loop stability.

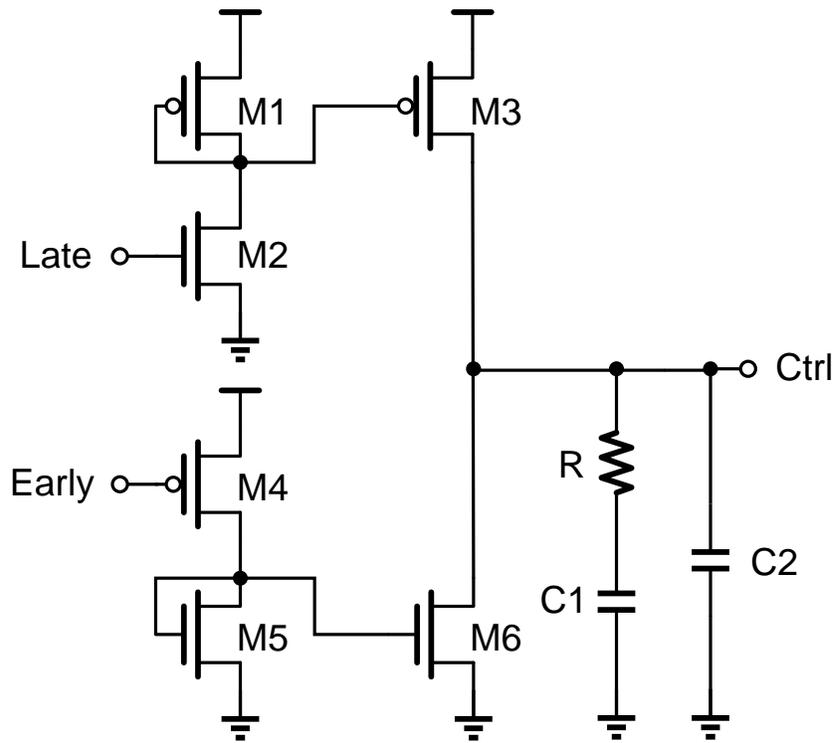


Figure 4.21 Schematic of Charge Bump and Loop Filter

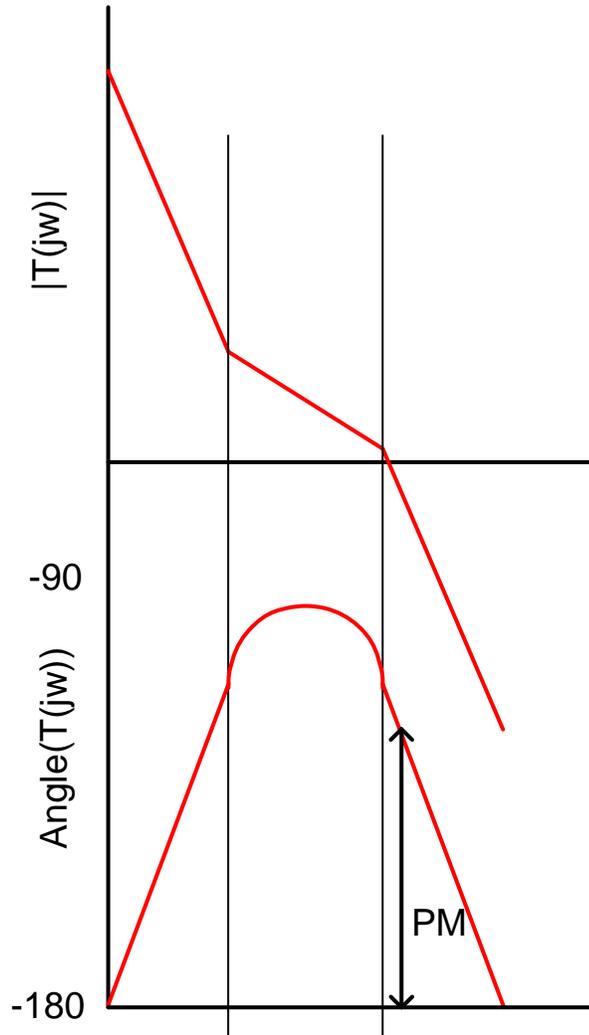


Figure 4.22 Phase Margin

4.4.4 VCO

An oscillator is an autonomous system that generates a periodic output without any input. Generally there are two types of oscillators, LC tank oscillator and ring oscillator. LC tank oscillators feature high accuracy and good phase noise, thus are widely used in wireless communication systems and high-speed IO clock sources. Ring oscillators, on the other hand, provide relatively wider tuning range and multiple output phases, are suitable for monolithic

systems design using any digital CMOS fabrication process. They are popular in CDR circuits and on-chip clock distribution. A voltage controlled ring oscillator is shown in figure 4.23.

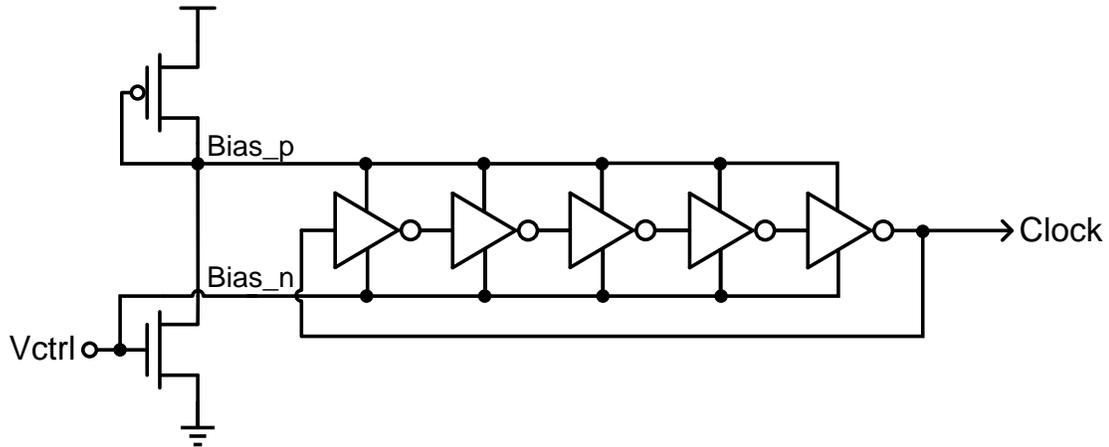


Figure 4.23 Schematic of Voltage Controlled Ring Oscillator

It comprises of two parts, a biasing generation and an inverter chain, as shown above. Frequency tuning can be done in various ways: by tuning the load capacitance, by tuning the driving strength, or by varying supply voltage. Figure 4.24 shows an implementation where the strength of an inverter is changed by adding two more transistors, M1 and M5, to the inverter structure, which is called single-ended current starve inverter. This type of stage offers great simplicity and power efficiency while suffers from common mode problems. More robust VCO such as differential ring oscillator can be used. Due to complexity and power constrains, single-ended ring oscillator is used in this design.

Important characteristics of ring oscillators include frequency, tuning range and VCO gain. The oscillation frequency is directly dependent upon the total delay around the loop. By

modifying the single stage delay and number of stages, the frequency can be adjusted. Fewer stages lead to less power consumption. Thus, one of the goals for this design is to reduce the number of stages. The tuning range is the range of oscillating frequency the VCO can achieve. It can be defined as a raw frequency or as normalized percentage. For this design, there is no need for a large tuning range. In order to achieve a relatively narrow tuning range of 10%, partially tuned current sources are introduced, shown in figure 4.24, in which M2 and M6 are always on. By adjusting the size of M1 and M5, tuning range can be changed. VCO (K_{VCO}) gain defines the change in output frequency divided by the change in control voltage. It can be regarded as the sensitivity of output frequency to the control voltage.

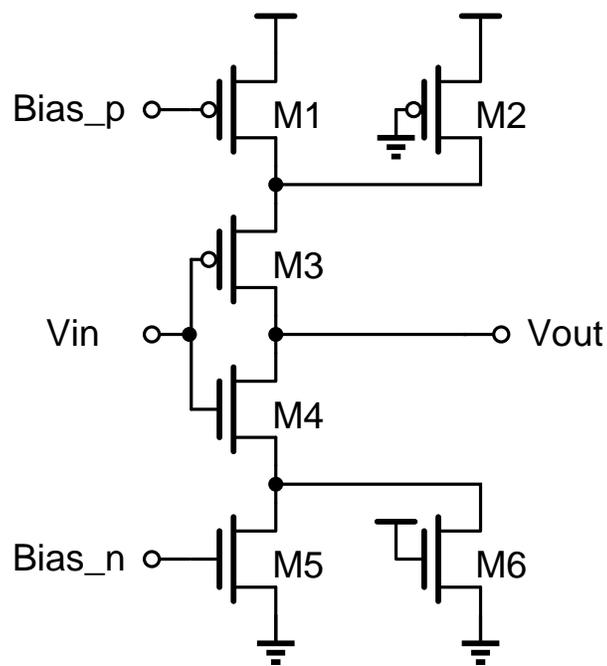


Figure 4.24 Single unit of Voltage Controlled Ring Oscillator

4.4.5 Results

Schematic simulation results of the PLL are shown in figure 4.25.

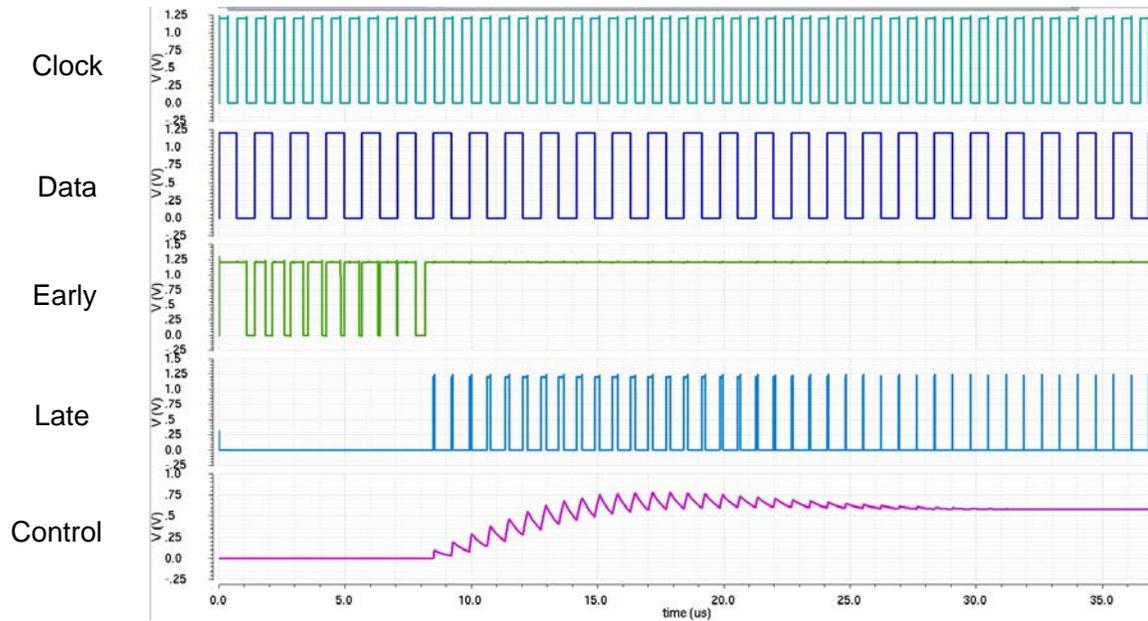


Figure 4.25 Schematic simulation result of clock recovery

4.5 Rectifier

All the circuits on the receiver side of this proposed headphone driver need to be powered wirelessly. A high frequency sine wave is transmitted onto the primary coil, coupled to secondary coil, and converted into DC power supply by a Rectifier, as shown in figure 4.26.

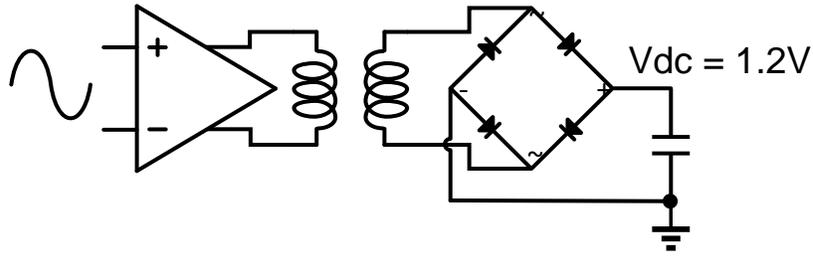


Figure 4.26 Powering scheme with LCI

An efficient power rectifier is required, which is able to provide stable 1.2 V power supply with a 50 mA peak current. Rectifiers can be broadly categorized in two types, half wave rectifiers and full wave rectifiers. The half wave rectifier is inefficient as it just uses one half of each complete sine wave of the RF signal to convert it to a DC voltage. In the other hand, full wave rectifier makes use of the entire input signal. Before analysis of several different topologies of full wave rectifier, the most important performance metric of rectifiers, Power Conversion Efficiency (PCE) should be mentioned here. PCE of rectifier is defined by the output power P_{OUT} divided by the input power P_{IN} . The input power can be written as the sum of output power and the loss of rectifier P_{LOSS} . Therefore, PCE can be written as follows:

$$PCE = \frac{P_{OUT}}{P_{IN}} = \frac{P_{OUT}}{P_{OUT} + P_{LOSS}} = \frac{P_{OUT}}{P_{OUT} + N \cdot P_{DIODE}}$$

Where N is the number of diode stages and P_{DIODE} is the power loss of each diode [29].

A conventional full wave rectifier, which is composed of multi-stage of voltage multiplier, is shown in figure 4.27.

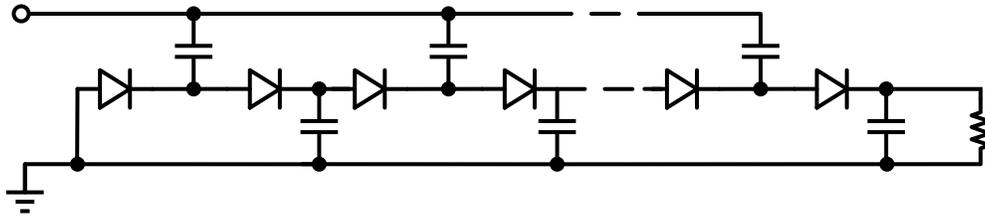


Figure 4.27 Multistage Voltage Multiplier

Let's start the analysis with a single stage Voltage Multiplier, as shown in figure 4.28:

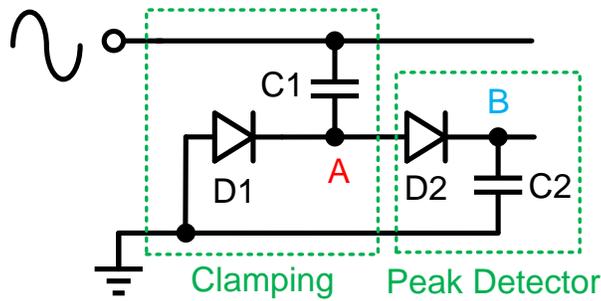


Figure 4.28 Single stage conventional rectifier

This single stage rectifier comprises of two parts, clamping and peak detector. Diode D1 will be on whenever voltage at node below $-V_T$, where V_T is the turn on voltage of diode. This operation makes sure that voltage at node A is always higher than $-V_T$. D2 and C2 form a peak detector, which detects the highest voltage from node A and keeps it at B. The overall waveforms are shown in figure 4.29. The output voltage of a single stage rectifier at node B is

$$V_{DC} = 2V_{RF} - 2V_T$$

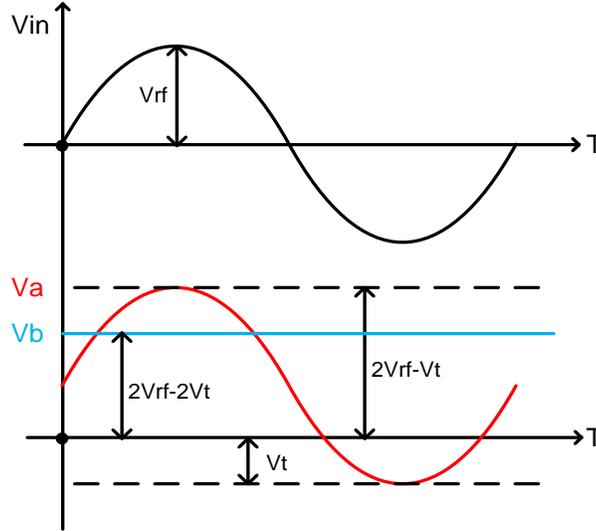


Figure 4.29 Waveforms of single stage rectifier

Note that the smaller the V_T is, the larger the V_{DC} becomes. For rectifiers with multiple stages, the output voltage will be

$$V_{DC} = N (2V_{RF} - 2V_T)$$

where N is the number of stages.

As shown in [30], the PCE formula for conventional rectifier circuits can be represented as:

$$PCE = \frac{V_{RF} - V_T}{V_{RF}}$$

Again, the smaller the V_T , the larger the PCE becomes. It can be said that the small V_T is essential in order to achieve large PCE of a rectifier.

In order to reduce the effective turn-on voltage for achieving larger PCE, several V_T cancellation schemes have been proposed [30]-[33]. Fig 4.30 shows the unit stage of a differential-drive CMOS rectifier circuit [34].

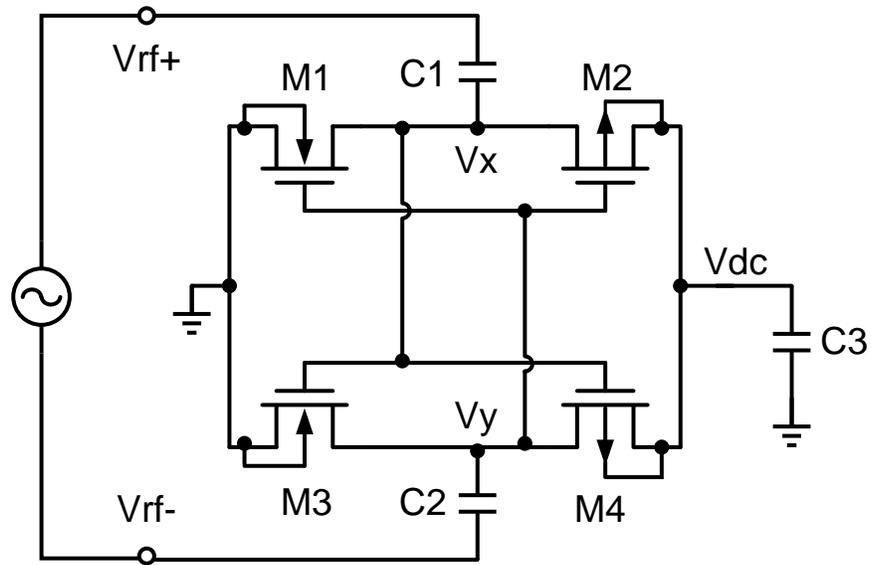


Figure 4.30 Single stage differential CMOS rectifier

Two V_T reduction schemes are used here. Voltage waveforms of internal nodes V_x and V_y obtained by simulation are shown in figure 4.31. NMOS transistor M1 and capacitor C1 together clamps V_x higher than $-V_T$, same as V_y . The DC components of V_x and V_y acts as a kind of static gate bias voltage compensating V_T , which is self- V_t -cancellation scheme [33]. In addition, in this differential structure, the gate of transistors is actively biased by a differential-mode signal. These two schemes together effectively reduces V_T and reverse leakage current.

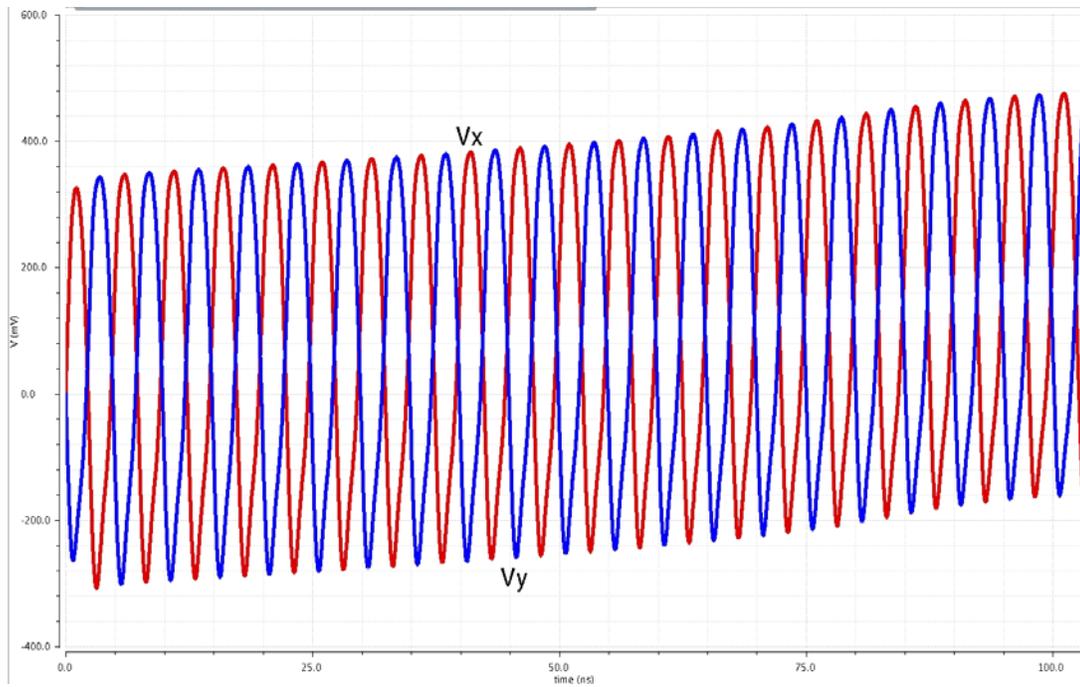


Figure 4.31 Internal node voltage waveform

Different operating conditions have been analyzed to achieve a high PCE as well as sufficient output voltage and current. The simulations are carried out with load resistance of 5 k Ω .

a. Amplitude of input sine wave

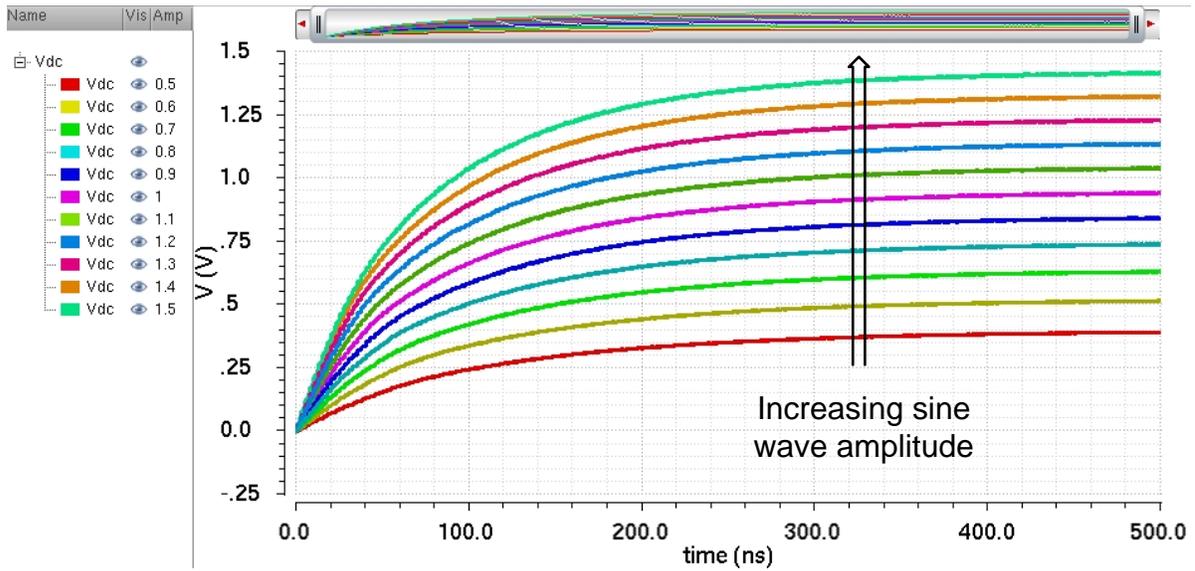


Figure 4.32 Simulated amplitude dependence of output DC voltage

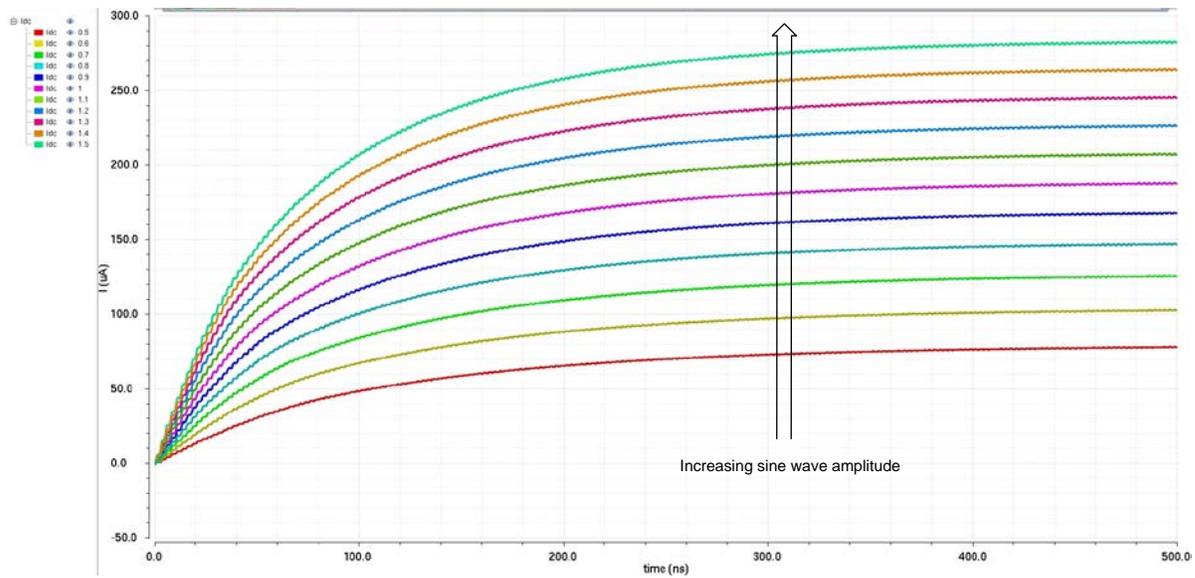


Figure 4.33 Simulated amplitude dependence of output DC current

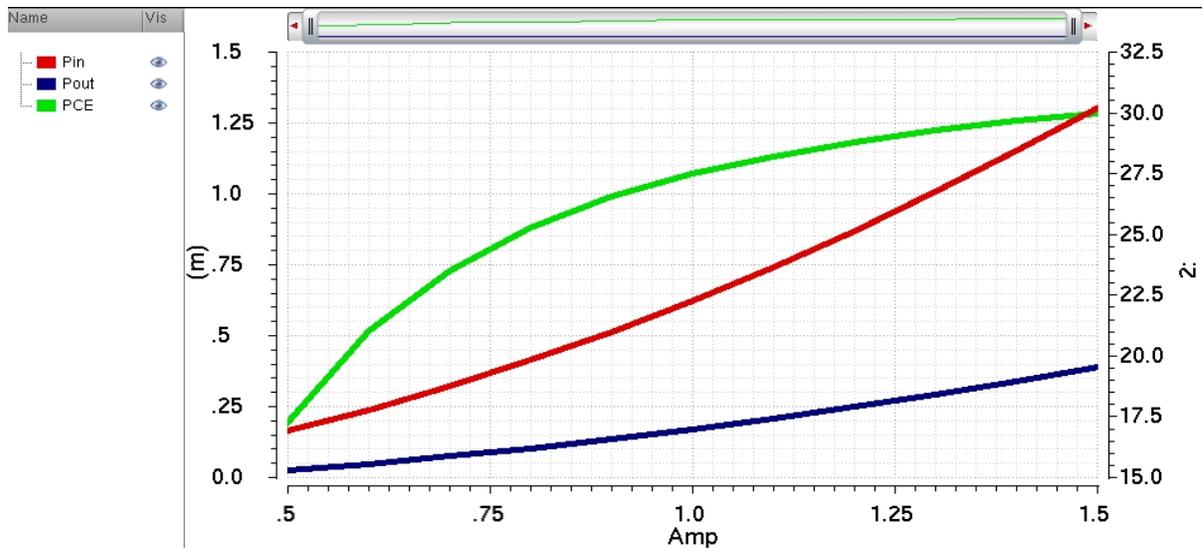


Figure 4.34 Simulated amplitude dependence of PCE

The amplitude of input sine wave is swept from 0.5 V to 1.5 V with 11 points. Figure 4.32 and 4.33 demonstrate that larger the input amplitude, higher the output DC voltage, as well as the output DC current. This is consistent with the above shown analysis of rectifier basics. Figure 4.34 shows PCE dependence on amplitude of input sine wave. PCE increases with higher amplitude. With a constant V_T , larger the input amplitude, higher PCE achieved. Therefore, besides reducing the value of V_T , increasing V_{RF} is another efficient way to increase PCE.

b. Frequency of input sine wave

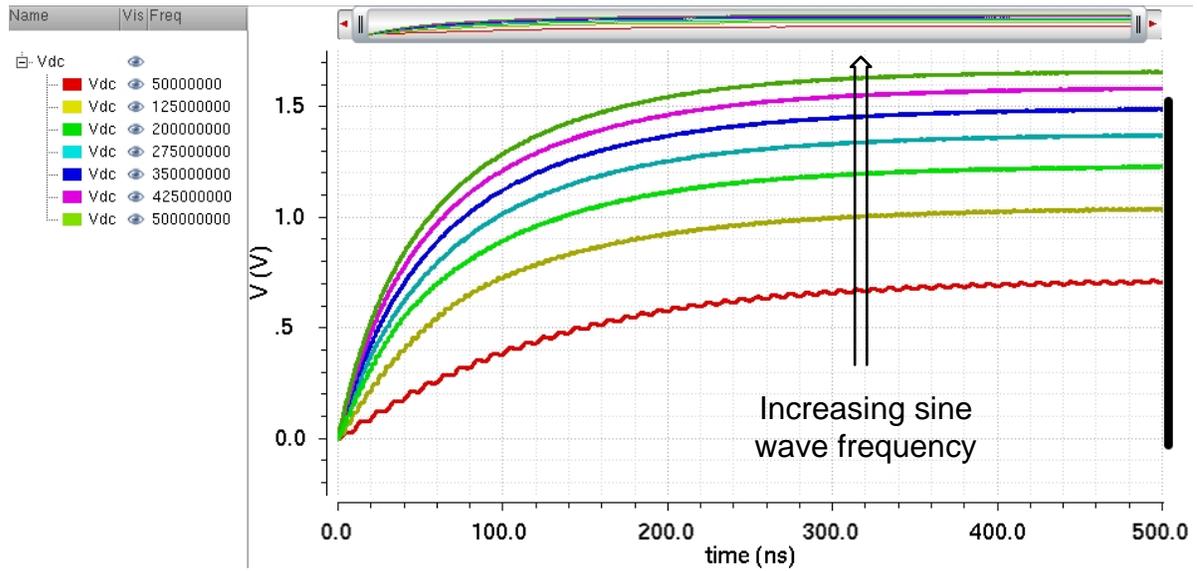


Figure 4.35 Simulated frequency dependence of output DC voltage

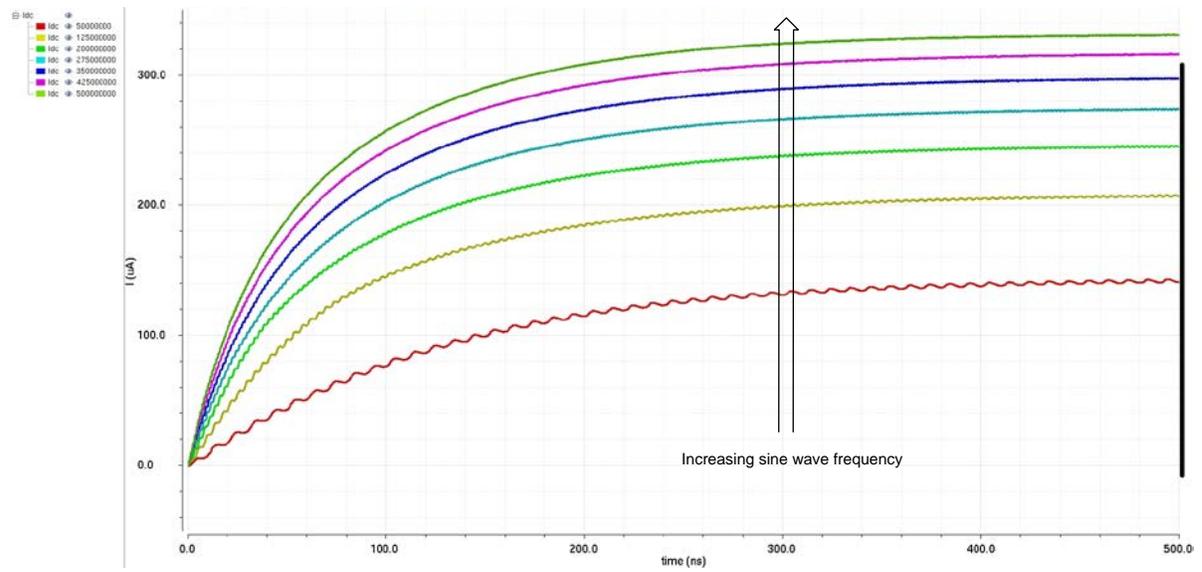


Figure 4.36 Simulated frequency dependence of output DC current

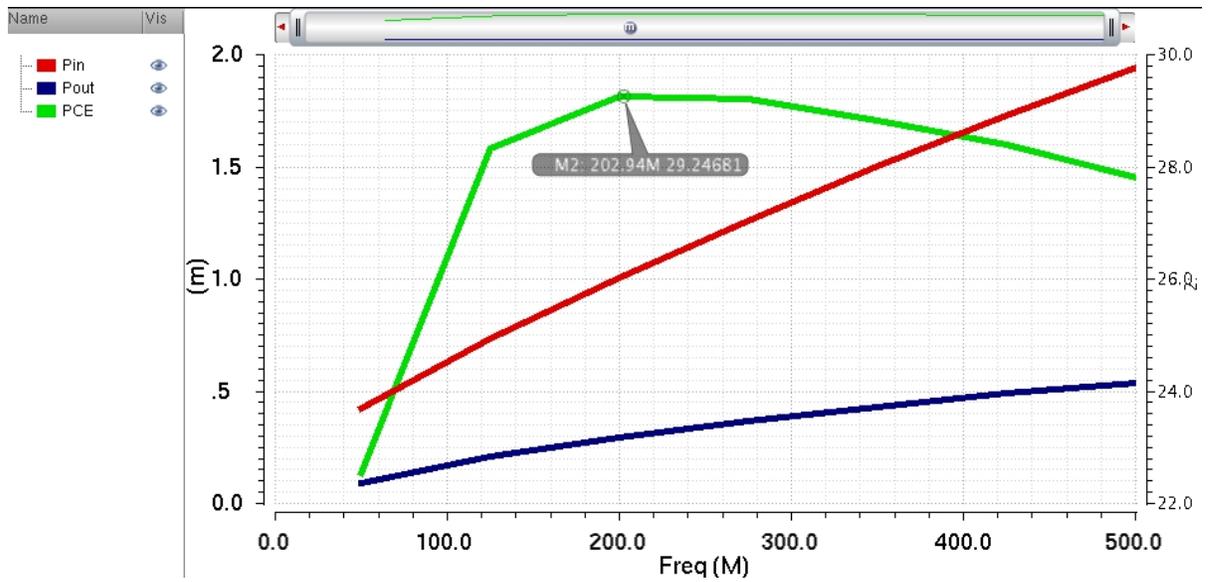


Figure 4.37 Simulated frequency dependence of PCE

The frequency of input sine wave is swept from 50 MHz to 500 MHz with 7 points. Figure 4.35 and 4.36 demonstrate that higher the frequency, higher the output DC voltage, as well as the output DC current. Figure 4.37 shows PCE dependence on frequency of input sine wave. PCE peaks at around 200 MHz, which is the operating frequency of this design. Input power almost linearly increases with frequency, while output power slows down. This is because energy loss caused by the parasitic resistance increases with the increase in the high-frequency current flow in the circuit due to the increase in the input reactance [34].

4.6 Results and Discussion

4.6.1 Layout

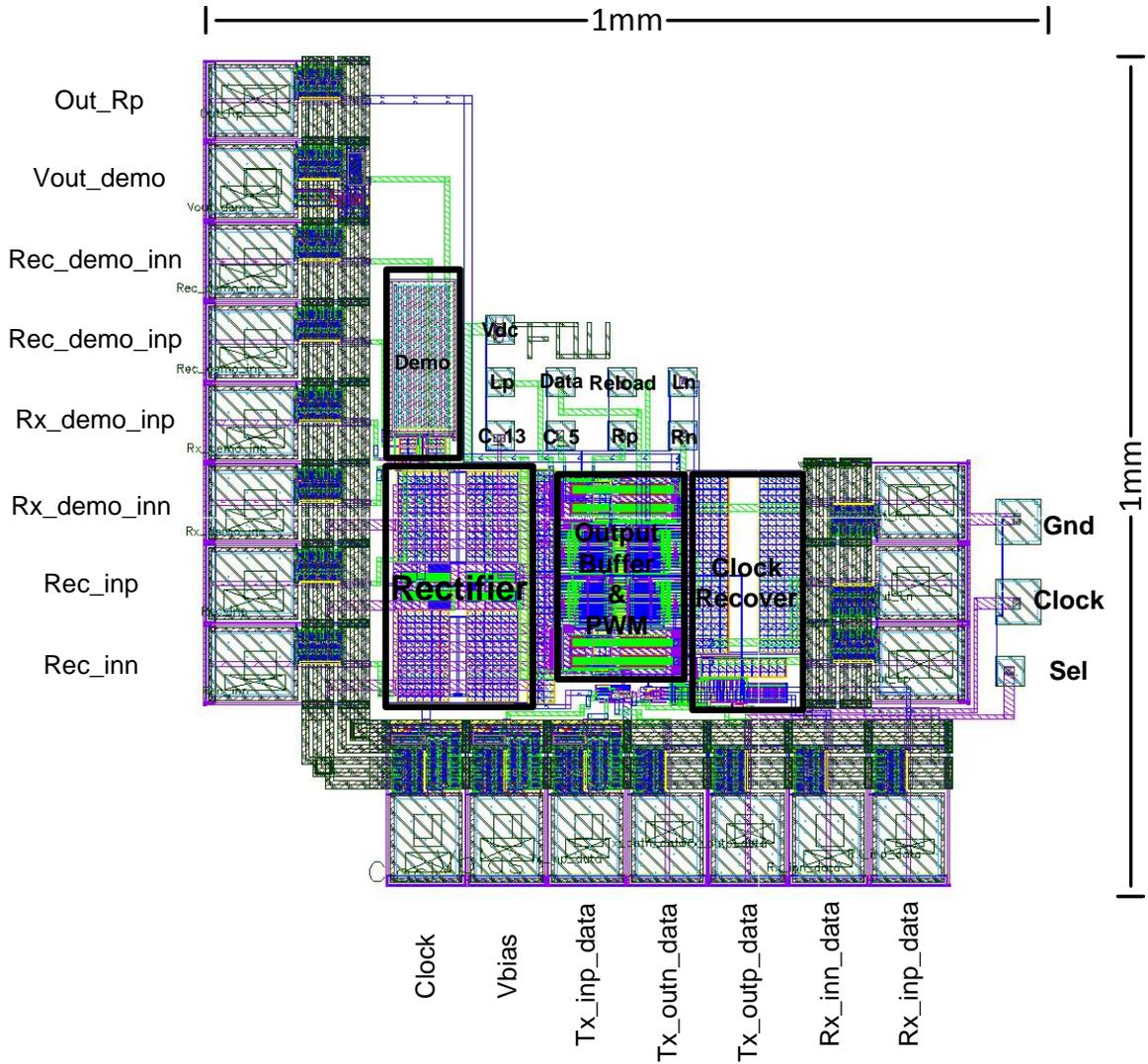


Figure 4.38 Layout with Pads and probing points

4.6.2 Simulation results

The entire design is simulated with a single tone 5 kHz audio, which is sampled at 44.1 kHz with resolution of 16 bits. A transient simulation result of voltage across 32 Ω load resistor is shown in figure 3.39 (a). The corresponding frequency spectrum of the output audio is calculated and plot in figure 3.39(b). It is clearly shown that the 5 kHz single tone is recovered, while generating more content at the harmonics of the original frequencies.

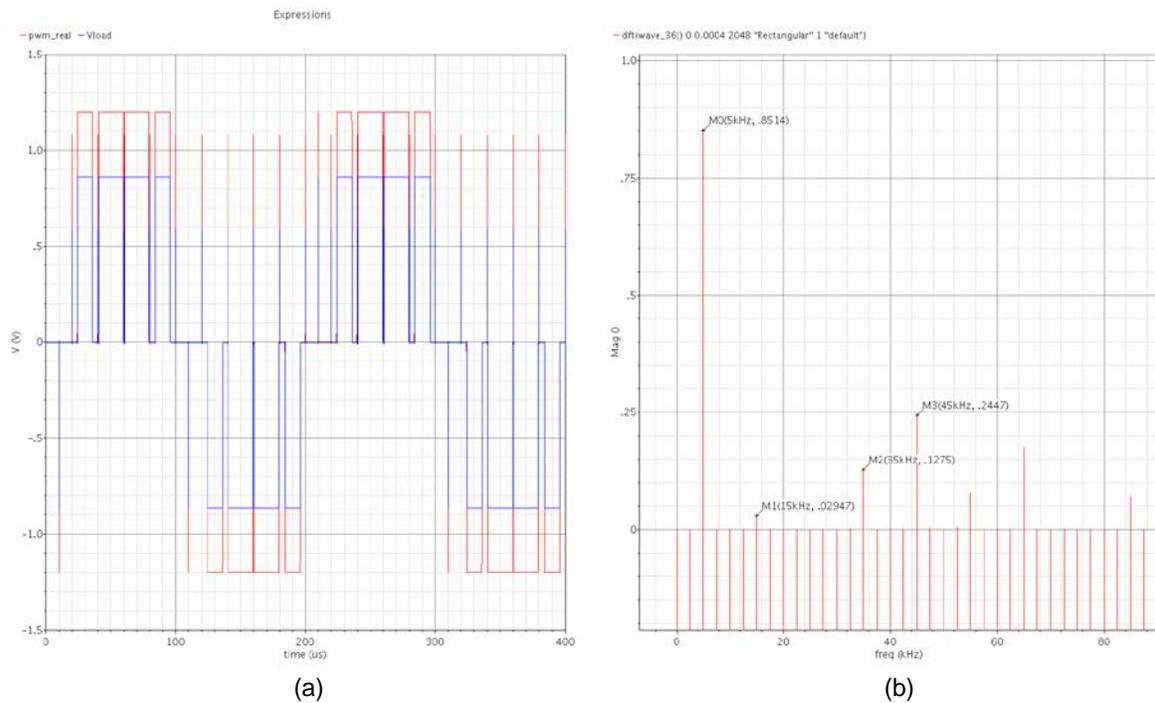


Figure 4.39 Simulated output waveform on 32ohm load (a) and corresponding frequency spectrum (b)

Table 4.1 summarizes the power dissipation of this design.

Table 4.1 Performance Matrix of Headphone driver with LCI

Technology		IBM 0.13 μ m CMOS
Area		1mm by 1mm
Power Dissipation	TX	3mW
	RX	1mW
	Deserializer	200 μ W
	Alignment	100 μ W
	Clock Recovery	400 μ W
	PWM Generator	400 μ W
	Output Buffer (include load)	50mW
Max data rate		2Gb/s

Chapter 5 Conclusion

5.1 Summary

In this thesis, several system design topologies of contactless headphone driver with inductive coupled interconnection have been proposed. (Ch3) Their advantages and disadvantages have been discussed. A self-synchronous, full digital and filterless topology is implemented in IBM's 0.13 μm 8RF process.

The differential CMOS rectifier previously used in RF harvesting field has been demonstrated to provide peak power of 60 mW, which is enough to drive all the circuitry at receiver side. (Ch4)

5.2 Future Work

The contactless headphone driver work can be extended in many directions.

5.2.1 Improvement of Disparity and Alignment Scheme

Clock recovery circuits require certain running disparity of transmitted data to reduce clock drifting due to the lack of edges in data. Coding schemes can be introduced to ensure running disparity, provide block alignment and error detection. The 8b10b encoding scheme, developed by IBM, has been widely adapted for this purpose.

5.2.2 Bi-directional Channel

a. Adaptive Powering

Due to the fast transition between different output currents in ternary PWM, the sine wave used for ac powering has to be amplitude modulated off-chip. This can be simplified by enabling feedback of PWM signal from receiver side to transmitter side. It requires a bi-directional inductive coupled channel which allows feedback control.

b. Contactless headset driver

A contactless version of today's widely used headset connector, TRRS, which enables both listening and talking.

5.2.3 Audio Quality Control

For demonstration purpose, this work does not focus much on improving audio quality. By introducing algorithmic-based PWM schemes, audio quality would be improved.

5.2.4 Data Modulation

By modulating data onto the sine wave, which is used for powering, will eliminate the use of data channel, and reduce overall area.

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